

NONDESTRUCTIVE EVALUATION

TECHNIQUE GUIDE

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NONDESTRUCTIVE EVALUATION TECHNIQUE GUIDE

By Alex Vary
Lewis Research Center

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NONDESTRUCTIVE EVALUATION TECHNIQUE GUIDEBOOK

by Alex Vary

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SUMMARY

A total of 70 individual nondestructive evaluation (NDE) techniques are described, each in a standardized single-page format for quick reference. Information is presented in a manner that permits ease of comparison of the merits and limitations of each technique with respect to various NDE problems.

An NDE technique classification system is presented. It is based on the system that was adopted by the National Materials Advisory Board (NMAB). The classification system presented herein follows the NMAB system closely with the exception of additional categories that have been added to cover more advanced techniques presently in use.

The rationale of the technique description format used herein is explained. The format provides for a concise description of each technique, the physical principles involved, objectives of interrogation, example applications, limitations of each technique, a schematic illustration, and key reference material. Cross-index tabulations are also provided so that particular NDE problems can be referred to appropriate techniques.

INTRODUCTION

The intent of this publication is to serve as a guidebook for the application of non-destructive evaluation (NDE) techniques in materials science and technology. The objective is to provide a quick survey of currently available techniques particularly for those who are unfamiliar with the wide range covered by NDE.

Nondestructive evaluation is a branch of materials science that is concerned with all aspects of the uniformity, quality, and serviceability of materials and structures. The science of NDE involves all technology for the detection and measurement of significant properties, as well as defects, in items ranging from research specimens to finished hardware and products. By definition, nondestructive techniques are the means by which materials and structures may be interrogated without disruption or impairment

of their serviceability. Using NDE, internal properties or hidden flaws are revealed or inferred by appropriate techniques.

NDE is becoming an increasingly vital factor in the effective conduct of research, development, and manufacturing programs. Only with the appropriate use of NDE techniques can the benefits of advanced materials science and technology be fully realized. However, the basic information required for appreciating the broad scope of NDE is rather widely scattered in a multitude of publications and reports. The purpose of this report, therefore, is to present a concise compilation of NDE technique information in a format that briefly reviews the essential data for each technique currently in use.

The term technique as used herein refers to the body of specialized procedures, methods, and instruments associated with each specific NDE approach or area. There are usually numerous methods or modes of procedure associated with each technique. The objective herein is to identify, classify, and describe techniques without giving details on methods of application or procedures. The format adopted provides a resumé of each technique on a single page for quick reference.

MODE OF PRESENTATION

CLASSIFICATION OF TECHNIQUES

In its report (ref. 1), the National Materials Advisory Board (NMAB) Ad Hoc Committee on Nondestructive Evaluation adopted an NDE technique classification system that divided techniques into six major categories: visual, penetrating radiation, magnetic-electrical, mechanical vibrations, thermal, and chemical-electrochemical. A modified version of the NMAB classification system is presented in this report. Additional categories have been included herein in order to cover advanced techniques that are properly classed under NDE. The resultant classification system is described in table I. The first six categories involve basic physical processes that require the transfer of matter and/or energy with respect to the object being interrogated. The last two are auxiliary categories involving processes that provide for the transfer and accumulation of information. The techniques in the last two categories constitute the processing and, in essence, "nondestructive" evaluation of the raw signals and images produced by the more basic processes.

TECHNIQUE DESCRIPTION FORMAT

In order to describe each NDE technique on a single page, a concise method of exposition was adopted. Each page takes the form of a tabulation consisting of six block

TABLE I. - NONDESTRUCTIVE EVALUATION TECHNIQUE CATEGORIES

Categories	Objectives
BASIC CATEGORIES	
Mechanical-optical	Color; Crack; Dimensions; Film thickness; Gauging; Reflectivity; Strain distribution and magnitude; Surface finish; Surface flaws; Through cracks
Penetrating radiation	Bond separation; Cracks; Density; Density and chemistry variations; Elemental distribution; Foreign objects; Inclusions; Microporosity; Misalignment; Missing parts; Segregation; Shrinkage; Thickness; Voids
Electromagnetic-electronic	Alloy content; Anisotropy; Cavities; Cold work, Local strain, Hardness; Composition; Contamination; Corrosion; Cracks; Crack depth; Crystal structure; Electrical and thermal conductivity, Flakes; Heat treat; Hot tears; Inclusions; Ion concentrations; Laps; Lattice strain; Layer thickness; Moisture content; Polarization; Seams; Segregation; Shrinkage; State of cure; Tensile strength; Thickness; Unbond
Sonic-ultrasonic	Crack initiation and propagation; Cracks, Voids; Damping factor; Degree of cure; Degree of impregnation; Degree of sintering, Delaminations; Density; Dimensions; Elastic moduli; Grain size; Inclusions; Mechanical degradation; Misalignment; Porosity; Radiation degradation; Structure of composites; Surface stress; Tensile, shear and compressive strength; Unbonds; Wear
Thermal	Bonding; Composition; Emissivity; Heat contours; Plating thickness; Porosity; Reflectivity; Stress; Thermal conductivity; Thickness; Voids
Chemical-analytical	Alloy identification; Composition; Cracks; Elemental analysis and distribution; Grain size; Inclusions; Macrostructure; Porosity; Segregation; Surface flaws
AUXILIARY CATEGORIES	
Image generation	Dimensional variations; Dynamic performance; Flaw characterization and definition; Flaw distribution; Flaw propagation; Magnetic field configurations
Signal-image analysis	Data selection, processing, and presentation; Flaw mapping, correlation, and identification; Image enhancement; Separation of multiple variables; Signature analysis

headings: METHOD, PRINCIPLES, OBJECTIVES, APPLICATIONS, LIMITATIONS, and REFERENCES and an illustration. There are standard subheadings in each block to further organize the presentation of information. The ensuing paragraphs explain the mode of presentation and terminology used in the technique description format.

Technique

The technique name appears at the top of each form and is the one commonly used in

the literature. However, there are cases where different names are used for the same technique. For these cases, the alternative names are given in the REFERENCES block. Alternative technique names are cross referenced in the TECHNIQUE NAME INDEX.

Method

To further identify each technique, the METHOD block describes the key process and basic result. This is given in terms of the principal energy, matter, or information transfer process involved. The method description is usually divided into two brief sentences that concisely describe the technique and its basic results.

Principles

Each technique can be completely characterized in terms of five principal factors:

- (1) Medium or energy source used to probe the interrogated object (e.g., X-rays, ultrasonic waves, and thermal radiation)
- (2) Nature of the signal, image, and/or signature resulting from interaction with the object (e.g., attenuation of X-rays, and reflection of ultrasound)
- (3) Method (or methods) of detecting or sensing the resultant signals (e.g., photo-emulsion, piezoelectric crystal, and inductance coil)
- (4) Method (or methods) of indicating and/or recording the signals (e.g., meter deflection, oscilloscope trace, and radiograph)
- (5) Basis (or bases) for interpreting the results (e.g., direct or indirect indication, qualitative or quantitative, and pertinent dependencies)

One or two lines of descriptive terminology corresponding to each of these five factors is given in the PRINCIPLES block.

Objectives

The attributes for which test objects are scrutinized are listed as subheadings in the OBJECTIVES block. These attributes are

- (1) Discontinuities and separations (cracks, voids, inclusions, delaminations, etc.)
- (2) Structure or malstructure (crystalline structure, grain size, segregation, mis-alignment, etc.)
- (3) Dimensions and metrology (thickness, diameter, gap size, flaw size, etc.)
- (4) Physical and mechanical properties (reflectivity, conductivity, elastic modulus, sonic velocity, etc.)

TABLE II. - SPECIFIC OBJECTIVES OF NONDESTRUCTIVE EVALUATION TECHNIQUES

Main objectives	Specific objectives	Specific attributes measured or detected
Discontinuities and separations	Surface flaws	Roughness, scratches, gouges, crazing, pitting, inclusions, and imbedations
	Surface-connected flaws	Cracks, porosity, pinholes, laps, seams, folds, and inclusions
	Internal flaws	Cracks, separations, hot tears, cold shuts, shrinkage, voids, lack of fusion, pores, cavities, delaminations, debonds, poor bonds, inclusions, and segregations
Structure or mal-structure	Microstructure	Molecular structure; crystalline structure and/or strain; lattice structure, strain, dislocation, vacancy, and/or deformation
	Matrix structure	Grain structure, size, orientation, and phases; sinter and/or porosity; impregnation; filler and/or reinforcement distribution; anisotropy; inhomogeneity; and segregation
	Small structural flaws	Leaks (lack of seal/throughholes), poor fit, poor contact, loose parts and/or particles, and foreign objects
	Gross structural flaws	Assembly errors, misalignment, poor spacing or ordering, deformation, malformation, and missing parts
Dimensions and metrology	Displacement and/or position	Linear measurement, separation, gap size, flaw size, depth, location, and orientation
	Dimensional variations	Unevenness, nonuniformity, eccentricity, shape and contour, size and mass variations (of entire object or part)
	Thickness or density	Film, coating, layer, plating, wall, and sheet thickness; density or thickness variations
Physical and mechanical properties	Electrical properties	Resistivity, conductivity, dielectric constant, and dissipation factor
	Magnetic properties	Polarization, permeability, ferromagnetism, and cohesive force
	Thermal properties	Conductivity, thermal time constant, and thermoelectric potential
	Mechanical properties	Compressive, shear, and tensile strength (and moduli); Poisson's ratio; sonic velocity; hardness; temper; and embrittlement
	Surface properties	Color, reflectivity, refraction index, and emissivity
Chemical composition and analysis	Elemental analysis	Detection, identification, distribution, and/or profile
	Impurity concentrations	Contamination, depletion, doping, and diffusants
	Metallurgical content	Variation; alloy identification, verification, and sorting
	Physicochemical state	Moisture content, degree of cure, ion concentrations, and corrosion and reaction products
Stress and dynamic response	Stress, strain, and/or fatigue	Heat-treatment, annealing, and cold-work effects; residual stress and strain; and fatigue damage and life (residual)
	Mechanical damage	Wear, spalling, erosion, and friction effects
	Chemical damage	Corrosion, stress corrosion, and phase transformation
	Other damage	Radiation damage and high-frequency voltage breakdown
	Dynamic performance	Crack initiation and propagation, plastic deformation, creep, excessive motion, vibration, and damping
Signature analysis	Electromagnetic field	Potential, strength, and field distribution and pattern
	Thermal field	Isotherms, heat contours, temperatures, heat flow, temperature distribution, heat leaks, and hot spots
	Acoustic signature	Noise; vibration characteristics; frequency amplitude, harmonic analysis and/or spectrum; sonic and/or ultrasonic emissions
	Radioactive signature	Distribution and diffusion of isotopes and tracers
	Signal or image analysis	Image enhancement and quantization; pattern recognition; densitometry; signal classification, separation, and correlation; flaw identification, definition (size, shape), and distribution analysis; flaw mapping and display

(5) Composition and chemical analysis (alloy identification, impurities, elemental distributions, etc.)

(6) Stress and dynamic response (residual stress, crack growth, wear, vibration, etc.)

(7) Signature analysis (image content, frequency spectrum, field configuration, etc.)

Terms used in this block are further defined in table II with respect to specific objectives and specific attributes measured, detected, defined, and so forth.

Applications

The APPLICATIONS block lists practical uses of the technique. Information in this block is divided into three groups. Each is covered by two subheadings. The first group includes the materials and the particular forms and features of these materials to which the technique applies. The second group includes on-line process- and quality-control uses. The second also lists uses for monitoring and/or examining equipment during operation and maintenance. The third group lists representative components, structures, assemblies, and systems to which the technique has been applied.

Limitations

The LIMITATIONS block gives conditions required by the technique:

(1) Conditions to be met for technique application (access, physical contact, preparation, etc.)

(2) Requirements to adapt the probe or probe medium to the object examined

This block also identifies factors that

(1) Limit the detection and/or characterization of flaws, properties, and other attributes

(2) Limit the interpretation of signals and/or images generated

References

The REFERENCES block names reference material in which additional information is available. In some cases, adequate standard reference material is unavailable; and in those cases, supplemental auxiliary sources are cited. If available, standards, specifications, and bibliographical sources are also listed. Usually, however, the primary reference for each technique will contain a good bibliography. Related or synonymous terms for the technique are also listed in this block along with closely related techniques.

All source references in this block are abbreviated but are fully designated in the REFERENCES section (p. 76). A general supplemental BIBLIOGRAPHY section (p. 84) follows the REFERENCE section.

Illustrations

A schematic diagram illustrates a typical version of the basic process, configuration, and instrumentation involved in applying the technique.

NONDESTRUCTIVE EVALUATION TECHNIQUE CATALOG

The technique description catalog that follows is organized in accordance with the eight categories given in table I. The techniques that are described are grouped and presented in the order indicated in the table of contents. An index of flaw types and a tabulated guide to the use of NDE techniques is given at the end of this report (p. 86).

Although the catalog that comprises the body of this report is comprehensive, it is not exhaustive. Many instances exist wherein a number of techniques are so similar that they are combined under one representative heading to avoid unnecessary repetition. Nevertheless, there are a number of techniques that are similar and yet must be listed separately because they are conventionally recognized as separate techniques with unique methodologies (e.g., X- and gamma radiography). Moreover, there is necessarily considerable overlap between some "auxiliary" and "basic" techniques. However, the auxiliary techniques do constitute specialized branches that are distinct from the basic techniques upon which they may be based (e.g., fluoroscopy and film radiography against X- and gamma radiography per se). The prime criterion for selection of techniques described herein was that of presenting a comprehensive account of the many separate arts and technologies that currently constitute the field of NDE. Overall, the catalog covers all the principal NDE techniques currently in use.

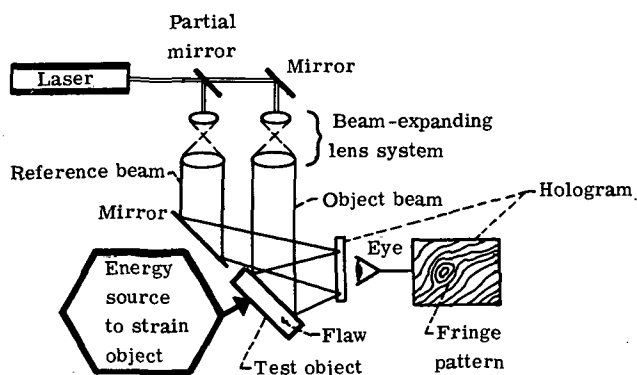
MECHANICAL-OPTICAL TECHNIQUES

Visual-Optical

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Direct visual and optically aided inspection is applied to object surfaces for indications of flaws and anomalies independently and in combination with other NDE techniques.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Visible light (ultraviolet light with fluorescent materials) Reflected or transmitted photons Eyes, optical aids, magnifiers, borescopes Visual image Direct; used with other techniques for direct interpretation (e.g., liquid penetrants, filtered particle, magnetic particle)
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Cracks, voids, pores, inclusions Roughness, grain, film (Mechanically aided) measurements ----- ----- Visible responses to stress -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Indefinite range of materials Surfaces, layers, films, coatings, entire objects On-line and off-line monitoring and control All forms of nondestructive inspection and testing Machined parts, internal surfaces; indefinite range of test objects, components assemblies, and systems
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Visual access Specialized optical aids usually required Various degrees of magnification Requires supplementation with other NDE techniques for flaw discrimination, detection, and measurement Hazard with ultraviolet light
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 2 (sections 10, 11, and 12) ----- ----- ----- Borescopy, refractometry, diffractometry, interferometry, reflectometry, microscopy, telescoping, light radiometry, phase-contrast, and schlieren techniques

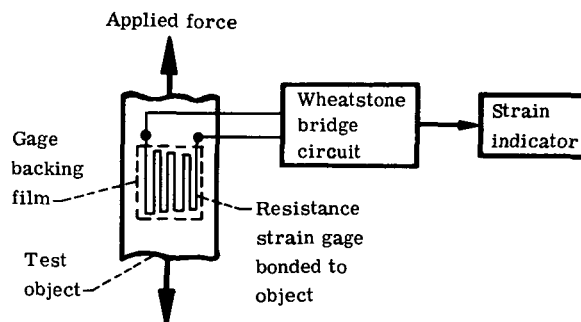
Holographic Interferometry

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Locates and measures surface microdisplacement and strain. Holographs made before and after stressing object are superposed to indicate subsurface and/or substrate strain or flaws.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Laser light and mechanical, thermal, and/or acoustic stressing Interference fringe pattern in superposed holograms Holographic reconstruction and photoemulsion Viewing through reference holograph Comparative or differential; becomes quantitative with fringe count or pattern calibration and/or standardization
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Delaminations, lack of bond, or poor bond Macrostructural variations (Wall) thickness variations Load response of structures; strain ----- Stress concentrations; vibration analysis Load transfer or distribution characteristics
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	All solids not plastically deformed by stress Surfaces and exposed areas of complex objects Inspection of welded, bonded, and fabricated parts Stress-strain patterns on parts and structures Aircraft and automotive tires, train wheels, airframes, wing panels, turbine blades and disks, nuclear fuel elements, honeycomb and composite structures
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Visual or optical access to test surface Laser illumination must be adequate to field viewed. Sensitive to half-wavelength surface displacements Ambient micromovements and noise patterns interfere. Optics or object isolation required to eliminate extraneous or ambient displacements; potential hazard from laser beam
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 3 (ch. 15) ----- ----- Holographic nondestructive testing (HNDDT) and holointerferometry Photoelastic coating, brittle coating, and strain gage



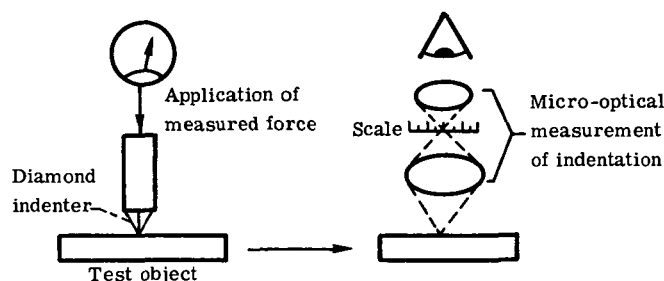
Strain Gage

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Electric resistance strain gage is bonded to surface of test object to indicate strain. Gage consists of fine wire or thin-foil grid layer sandwiched between layers of carrier material.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Electric current Variation of gage resistance Wheatstone bridge circuit Meter indication; potentiometer reading Direct indication which is quantitative and depends on uniformity, standardization, and calibration of gages
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	----- ----- ----- Microdisplacements, forces, torque, pressure, acceleration, and magnetostriction ----- Stress-strain response and/or properties, creep, and crack growth -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals, nonmetals, and/or composites Surfaces ----- Tensile testing, stress analysis, and strain monitoring Operating turbines, engines, airframes, ship hulls, cranes, earth-moving equipment, and pressure vessels
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Clean and prepared surface and access to critical area Application and orientation of gages critical Measures strain to order of 1 micrometer per meter Affected by temperature, humidity, moisture, and slippage Gage becomes permanently bonded to equipment.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 2 (section 54) ----- ----- Resistance gage Photoelastic coating, brittle coating, holographic interferometry, and mechanical strain gage



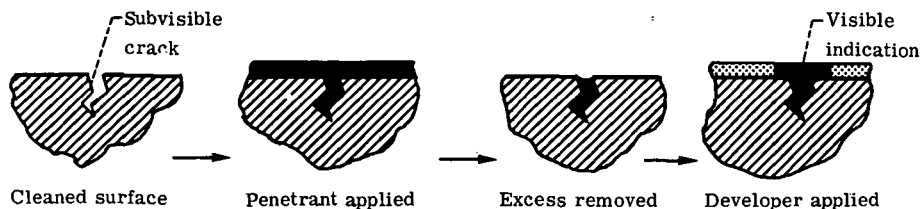
Microhardness

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Microindentation is made in test object surface. Microscopic measurement is made of indentation size to arrive at hardness value.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Specific diamond indenter applied with specific force Indentation of specific geometric shape Micro-optical comparator Visual and optical metrology Relative (hardness values computed from formulas and read from charts); calibration standards required
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	----- ----- ----- Hardness; tensile strength (qualitative) ----- ----- -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals Surface and/or substrate; small specimens and/or localized spots ----- ----- Metallurgical specimens
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Access to surface; surface grinding and/or polishing Special fixturing to align probe with surface Sensitivity affected by load perpendicularity, vibrations, and surface finish Tensile strength values inexact Limited to pointwise sampling
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	----- ----- Reference 4; ASTM E-384-70 Hardness indentation; hardness test, Knoop and Vickers -----



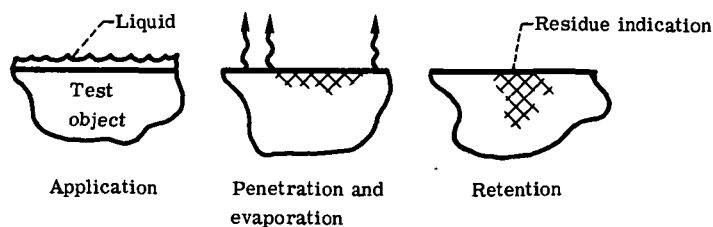
Liquid Penetrant

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Test surface is covered with penetrating liquid that seeks surface-connected cracks. Liquid in cracks bleeds out to stain powder-coating applied to surface after removal of excess liquid film from surface of test object.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Liquid medium containing dye or fluorescent substance Capillary bleedout of liquid trapped in flaws Localized staining of applied developer powder Direct visual observation for dye; black light for fluorescence Direct indication (dependent on proper methods for application of penetrant and developer)
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Cracks, pinholes, laps, seams, coldshuts, leaks ----- ----- ----- ----- Fatigue cracking and grinding cracks -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	All nonporous, nonabsorbing materials Surfaces, entire objects, and complex shapes Control step in metal processing and/or joining Cracks formed during testing and equipment operation Weldments, joints, tubing, castings, and billets; fuel and liquid-oxygen tanks and vessels, aluminum parts, gas turbine disks and blades, engine mounts, and gears
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Access required for surface decontamination and cleaning Discontinuity must be surface-connected and open Microcracks to order of 1-micrometer width False indications from shallow scratches and/or smearing Porosity of surface may mask important indications. Discontinuity depth is not indicated. Ultraviolet-light hazard (with fluorescent penetrants); vapor hazard.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 2 (sections 5 to 8) ----- Reference 4, ASTM E-165-65, E-270-68 Dye penetrants and fluorescent penetrants Filtered particle, electrified particle, magnetic particle, and radioactive gas penetrant



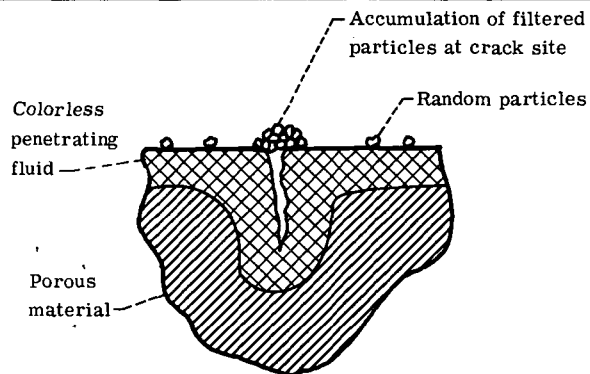
Volatile Liquid

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Thin layer of volatile liquid is applied to surface. The liquid evaporates uniformly except in areas that retain it as a result of porosity and/or cracks.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Volatile liquid (generally nondenatured ethanol) Retention of liquid (slow-drying areas) Visual: color and/or shading Visual Direct or differential; based on evaporation time
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Porosity (variations) ----- ----- ----- ----- ----- -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Porous solids Surfaces or surface-connected features ----- ----- Ceramics, graphite billets, rocket nozzles, solid rocket propellants, and ablative nose cones
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Surface access and clean lint-free surface required Lint-free applicator and totally and uniformly wetted surface required ----- Background and/or color may reduce differentiation of wetted areas. Requires heating to evaporate excess or residue; flammable liquid hazard
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 5 ----- ----- Alcohol wipe Filtered particle and electrified particle



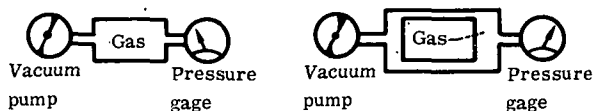
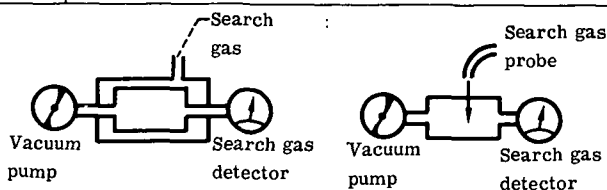
Filtered Particle

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Fluid-suspension of fine powder is sprayed on surface. Liquid is drawn into fine cracks leaving powder accumulation on surface at crack site.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Generally oil-base suspension of fine particles Accumulation of particles at edge of crack Visual examination for accumulations Dye or fluorescence; photography Direct; particle size, shape, concentration, and penetrating power of fluid critical
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Cracks and porosity Variations in absorption ----- ----- ----- ----- -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Porous solids (clay, carbon, powder metals, concrete, ceramics, cermets) Surfaces ----- ----- Grinding wheels and insulators
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Clean and accessible surface required Test-object pore size should be less than 100 mesh. Sensitive to microcracks to order of 100 micrometers Depth of flaw not indicated Residue removal required. Potential contamination. Cracks and/or pores must be open to surface. Skin irritants involved.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 2 (section 9) ----- ----- Fine particle (suspension) Liquid penetrants and volatile liquid



Leak Detection

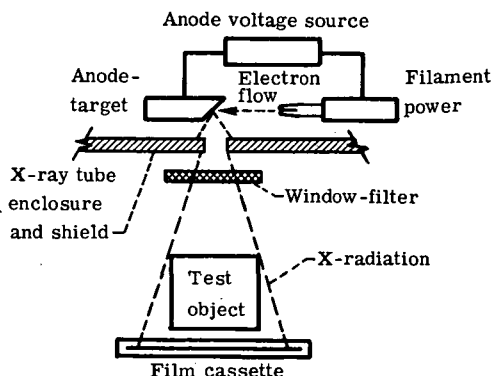
METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Exit of gas from or ingress of gas into sealed enclosure is induced. Enclosed or external search gas is used to locate and sense leaks and to estimate leak rate.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Search gas: helium, hydrogen, krypton-85. Leakage Spectrometer, counter, and vacuum or pressure gage Meter indication; audible signal Direct (standard reference leak required for quantitative indication)
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Through-holes and cracks Porosity and lack of seal ----- ----- ----- ----- -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals and mixed, nonporous materials Enclosures and seals Quality control of envelopes and seals Vacuum leak check of experimental and operating equipment Weld, braze, and adhesive bonds; glass envelopes; vacuum chambers; elastomer and metal gasket seals; reactor fuel pins; liquid-metal containers and components
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Direct access required to at least one side, indirect to the other Special probe or sniffer; object enclosure usual Sensitivity to order of 10^{-7} liter-nanobar per second ----- Location and size of leak are usually difficult to detect. Smeared metal or contaminants may plug leak passage. Radiation and other residual gas hazards are possible.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 6 (ch. 15) Reference 7 Reference 4; ASTM E-425-71, E-427-71, E-432-71 Helium leak check and pressure check Hydrostatic tests



PENETRATING RADIATION TECHNIQUES

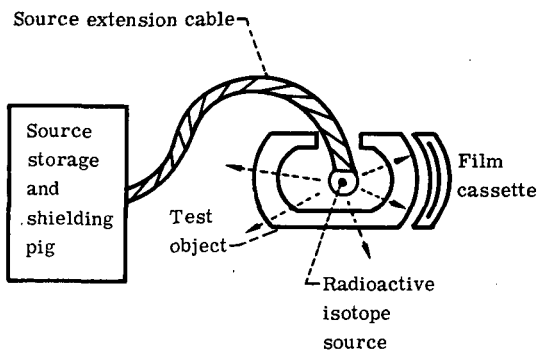
X-Radiography

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Penetrating radiation emitted by X-ray generator is imposed on test object. Radiation transmitted or attenuated by test object is used to image or detect internal structure and/or flaws.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	X-rays in 10^{-13} - to 10^{-9} -meter wavelength range Transmission or attenuation by object variables Photoemulsion, fluoroscope, and/or radiometer Radiographic image; densitometry Direct interpretation (standard penetrameters for image quality indication); control of contrast, resolution, and density critical
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Cracks, porosity, voids, and inclusions Internal malstructure, misassembly, or misalignment Thickness, diameter, gap, and position Density variations ----- Wear and corrosion -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals, nonmetals, composites, and mixed materials Entire objects or structures; wide range of shape and sizes Joining and welding quality control Loose or stray parts and breakage in mechanisms Castings; welds; braze distribution; electronic assemblies; rocket propellant encasements; and aircraft, space, and automotive components and/or systems
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Access to opposite sides of test object required Voltage, exposure time, and focal spot size critical Density and thickness variations to order of 2 percent Sensitivity decreases with increasing thickness. Cracks must be oriented parallel to beam. Radiation hazard.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 2 (sections 17, 21, 24, and 25) Reference 8 Reference 4; ASTM E-142-68; E-94-68 Film radiography Gamma radiography, neutron radiography, autoradiography, and microradiography



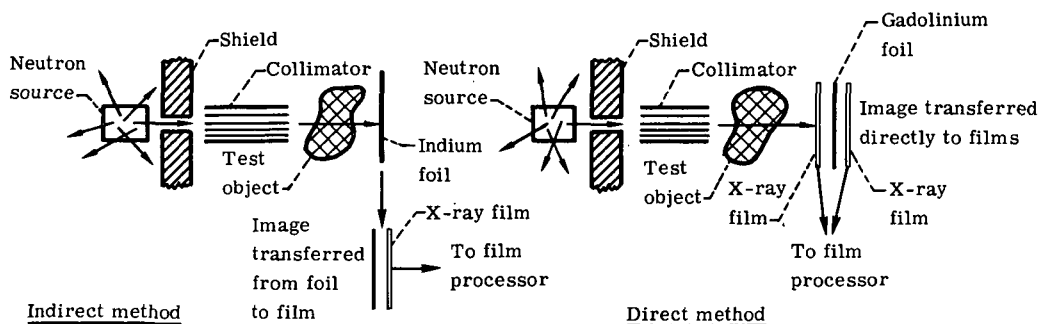
Gamma Radiography

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Penetrating radiation emitted by isotope source is imposed on test object. Radiation transmitted or attenuated by test object is used to image or detect internal structure and/or flaws in thick cross sections of dense materials.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Gamma radiation in 10^{-13} - to 10^{-9} -meter wavelength range Transmission or attenuation by object variables Photoemulsion and/or radiometer Radiographic image; densitometry Direct interpretation (standard penetrameters for image quality indication); control of contrast, resolution, and density critical
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Cracks, porosity, voids, and inclusions Internal malstructure or malformation Dimensional variations and anomalies, thickness, and gaps Density variations ----- ----- Panoramic imaging
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Usually applied to dense or thick metallic materials Entire objects or structures; range of shapes and sizes ----- ----- Castings, thick or large components, and especially configurations not accessible to X-ray generators
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Often requires fitting source inside complex parts Special mechanism for remote extension of source to part Density or thickness variations to order of 2 percent Sensitivity usually less than with X-rays Cracks must be oriented parallel to rays. Source energy uncontrollable and decays with time. Radiation hazard.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 2 (section 15) Reference 8 Reference 4; ASTM E-280-68, E-94-68 ----- X-radiography and neutron radiography



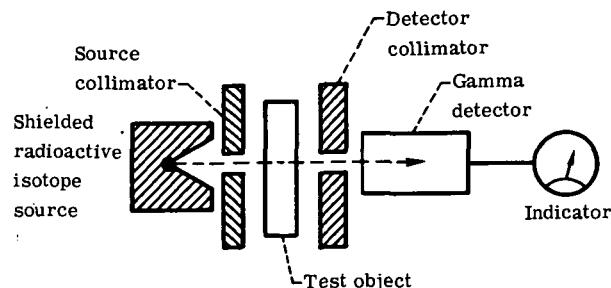
Neutron Radiography

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Neutron beam from reactor, accelerator, or isotope source is imposed on test object. Neutrons transmitted or attenuated by test object are used to image or detect internal structure and/or flaws that are poorly revealed by X- and gamma radiation.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Thermal or epithermal neutron beam Transmission or attenuation by object variables Activation of metallic foil and indirect transfer to photoemulsion Radiographic image; densitometry Direct interpretation (standard penetrameters for image quality indication); control of contrast resolution and density critical
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Voids, porosity, inclusions, and cracks Internal malstructure, anomalies, and/or misalignment Thickness, diameters, and gaps ----- Contamination; element and/or isotope distribution and/or identification ----- -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED ----- PROCESS CONTROL APPLICATIONS ----- IN SITU AND DIAGNOSTIC APPLICATIONS ----- EXAMPLE STRUCTURES AND COMPONENTS	Metals, nonmetals, composites, and mixed materials Entire objects or structures; range of shape and sizes ----- ----- Pyrotechnic devices, resins, plastics, organic substances, honeycomb structures, integrated microcircuits, nuclear fuel elements, radioactive materials, high-density metals, materials containing hydrogen
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS ----- OTHER CONDITIONS AND LIMITS	Access to interpose object between source and detectors Collimation, filtering, and moderation of neutron beam Density or thickness variations to order of 2 percent Sensitivity decreases with increasing thickness. ----- Cracks must be oriented parallel to beam. Image quality varies with neutron source. Radiation hazard.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 9 Reference 8 ----- Neutrography X-radiography and gamma radiography



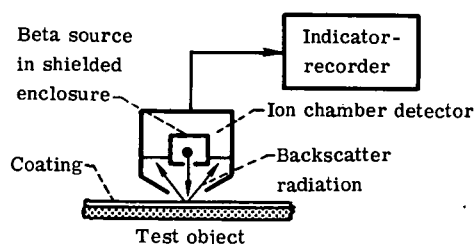
Penetrating Radiometry

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Penetrating radiation is directed through selected small areas of test object and radiation intensity emerging on opposite side is measured. This provides a more precise measure of attenuation than X- or gamma-radiography.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	X, gamma, or beta-particle radiation Attenuation of transmitted radiation Crystal and/or scintillation detector Meter deflection; coordinate plot Comparative and differential; quantitative with standards of comparison
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Voids, inclusions, and porosity ----- Thickness Density ----- ----- -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals, nonmetals, composites, and mixed materials Platelike, rodlike, or uniform shapes; coatings; and foils In-line monitoring of metal and other processing Resin-to-fiber ratio evaluation in laminar composites Sheet, plate, strip, tube, plated parts, and reactor fuel rods and/or plates
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Access to interpose object between source and detector Beam size and alignment critical Transmission variations to order of 0.2 percent Nature of flaw may be ambiguous as a result mixed effects. Beta radiation applies to ultrathin sheet and coatings. Radiation hazard.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 2 (section 18) ----- ----- Isotope gaging, gamma radiometry, X-radiometry, X-ray thickness gage, radiosotope thickness -----



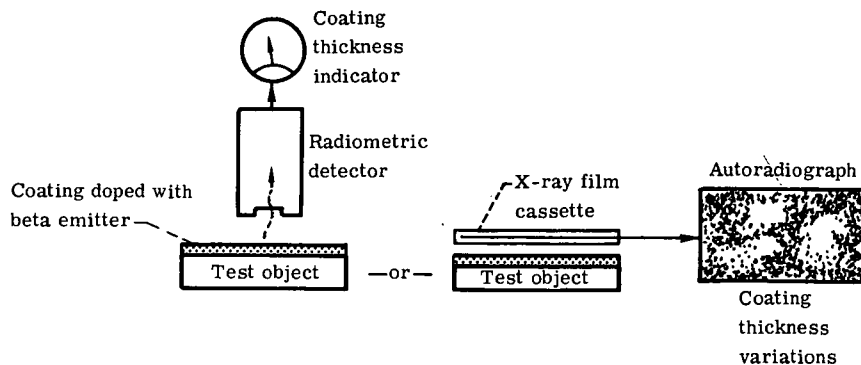
Backscatter Radiometry

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Backscatter, gamma, or X-rays are impinged on a surface layer, and a detector measures backscatter rate and intensity as an indication of fine variations in coating and/or surface layer thickness and elemental distributions.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Beta particles, soft gamma, or X-rays from small source Backscattered betas or radiation Counter; radiometer Meter deflection; coordinate plot Comparative or differential; becomes quantitative with the use of reference standards and/or calibration
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	----- ----- Thickness ----- Elemental distributions and analyses ----- -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals, nonmetals, and composites Coatings, layers, films, substrates, and surfaces Thickness monitoring ----- Paint, plastic coatings, and composite laminates; identification and analysis of alloys, solutions, and ores
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Close proximity to surface required Special miniaturized probes required for adequate spatial resolution Thickness variations to order of 10 micrometers Ambiguous response from mixed variables Low-energy radiation
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 6 (ch. 14) References 10 and 11 ----- Beta-backscatter and gamma-backscatter Penetrating radiometry and Mössbauer analysis



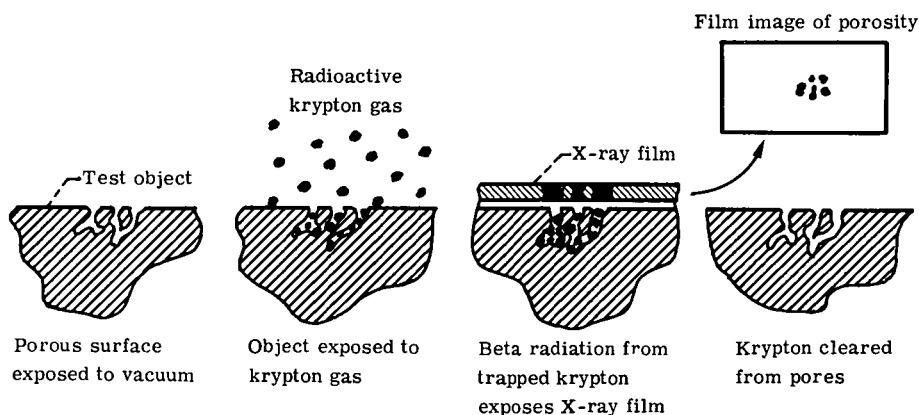
Autoradiography

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Isotopic radiation emitted by test object is utilized. Radiometry or radiography detects and measures the distribution and quantity of radioactive species.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Radioisotopes incorporated in test object or naturally radioactive materials Beta or gamma radiation Crystal and/or scintillation detector and/or counter; photoemulsion Meter deflection, radiograph, and/or coordinate plot Differential; quantitative with calibration
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	----- Continuity and homogeneity Thickness ----- Element and isotope distribution and identification Stress and/or thermal effects; wear, erosion, and/or abrasion; chemical reaction rates -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals, nonmetals, and composites Surfaces and/or substrates, and coatings Coating application, thickness, and/or continuity Maintenance evaluation of protective surfaces Silicide coatings, nuclear fuel elements, geological specimens, minerals, and ores
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Close access to surface Incorporation of radioisotopes for labeling Beta penetration limited to order of 100 micrometers Analytical sensitivity depends on background radiation. Potential hazard in radioactive dust from surface
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	References 12 and 13 ----- ----- ----- ----- Radioactive labeling and tracer autoradiography



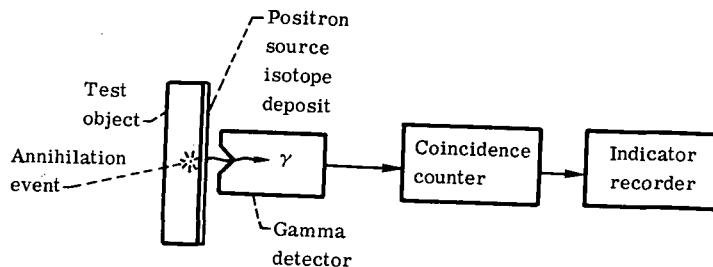
Radioactive Gas Penetrant

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Radioactive gas penetrates surface-connected discontinuities. Beta radiation from gas adsorbed in cracks and pores is detected and indicates distribution and size of flaws.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Radioactive gas molecules, usually krypton-85 Localized beta and gamma emission Crystal detector; photoemulsion Meter deflection; radiograph Direct indication; dependent on proper controlled procedures for material preparation and penetration
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Cracks and pores ----- ----- ----- Oxidation and corrosion Friction, wear, erosion, and abrasion effects -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals and nonporous or nonabsorbent solids Surfaces and substrates ----- ----- Metallurgical specimens, engine components, bearings, and turbine disks and blades
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Surface cleaning and penetration method critical Flexible photoemulsion base or spray coating Crack width to order of 0.01 micrometer Extremely sensitive to spurious marks and scratches Flaw depth must be inferred. Radiation hazard, requires gas recovery system.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 14 ----- ----- Kryptonation Autoradiography



Positron Annihilation

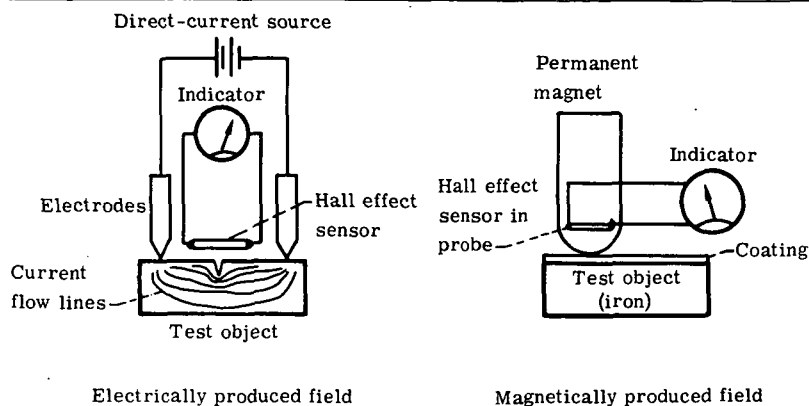
METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Beam of positrons penetrates specimen subsurface. Gamma photons resulting from positron annihilation are more copiously emitted at loci with microstrain or electron concentrations.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Positrons from isotope deposit on specimen surface Count of positron annihilation events Gamma detector and coincidence counter Counter display Differential analysis based on event rate intervals between e^+ and γ emissions
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Lattice dislocations and/or vacancies Plastic strain loci ----- ----- ----- Overaging or reversion, incipient cracking, fatigue, localized work-hardening, and annealing -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals (such as aluminum and copper alloys) Subsurfaces and substrates ----- ----- Experimental specimens
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Close proximity to surface Deposition of isotope or source on surface required Subsurface penetration range of order of 1 millimeter Nanosecond time intervals are significant. Technique is experimental. Radiation hazard.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 15 ----- ----- ----- -----



ELECTROMAGNETIC-ELECTRONIC TECHNIQUES

Static Magnetic Field

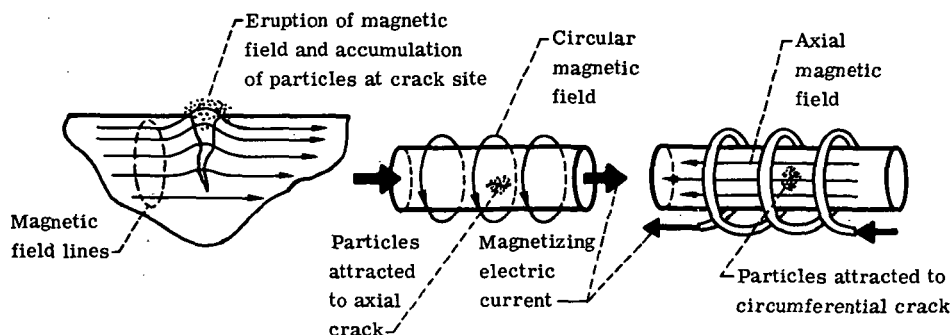
METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Magnetic field is imposed on test object. Field permeates and magnetizes object and test zone and probe scans and detects field perturbations that are characteristic of surface and/or subsurface flaws and anomalies.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Static magnetic field induced or superposed on object Field gradient and normal or tangential perturbations Rotating or oscillating coil; Hall or Foerster probe Meter deflection; coordinate plot and field map Comparative or differential; requires standard defects for comparison
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Cracks, inclusions, gouges, scratches, holes, and pores Magnetic anisotropy Thickness Coercive force, magnetic permeability, hardness Compositional variations ----- Magnetic field strength, signature, and characteristics
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Ferromagnetic and permeable metals Surfaces and substrates; uniform and regular shapes Feedback sorting ----- Nonmagnetic coating thickness, depth of case hardening, analysis of carbon content in steels, bearing raceways, gear teeth
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Very near proximity of probe to surface Specialized probes usual for various measurements Cracks to order of 0.03 millimeters Ambiguities arise because of edge and/or lift-off effects. Access to both sides for some thickness measuring; does not discriminate among types of flaws
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 2 (sections 33 and 34) References 16 and 17 ----- Magnetic field perturbation and magnetic field test Magnetic particle and eddy current



Magnetic Particle

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Test object or part is magnetized. Magnetic powder applied to surface accumulates over regions where magnetic field erupts or emerges as a result of surface or subsurface flaws.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Magnetizing current or field imposed on part Field distortion or leakage at surface Accumulation and pattern of magnetic powder clusters; pattern in magnetic tape ^a Visual, photography, and magnetic tape and/or rubber Direct indication, depends on direction and strength of magnetic field and on powder and vehicle control
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Cracks, seams, pores, and inclusions ----- ----- Permeability variations ----- ----- -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Ferromagnetic materials Surface and substrate; regular and uniform shapes ----- ----- Bars, forgings, weldments, extrusions, fasteners, engine components, shafts, and gears
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Requires clean and relatively smooth surface Fixturing required to hold and magnetize part Cracks to order of 0.5-millimeter major dimension Field alignment and strength critical Followup metal removal may be required. Part demagnetization may be problematic. Removal of powder and vehicle required.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 2 (sections 30 to 32) Reference 18 Reference 4; ASTM E-109-63(71), E-138-63(71), E-269-68 Magnetic tape and magnetic rubber Magnetic field perturbation and eddy current

^aAlso field set into room-temperature vulcanizing magnetic silicone rubber replication of magnetized part.



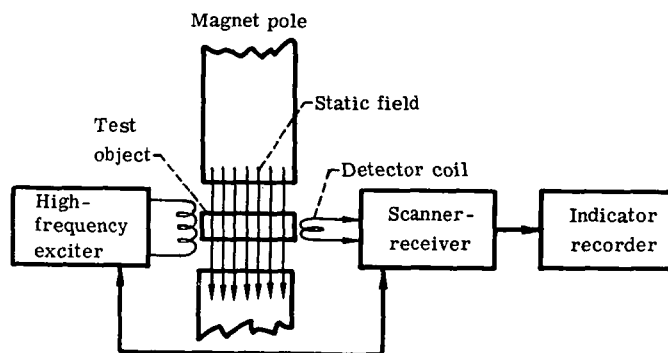
Principle of indication

Circular magnetization method

Axial magnetization method

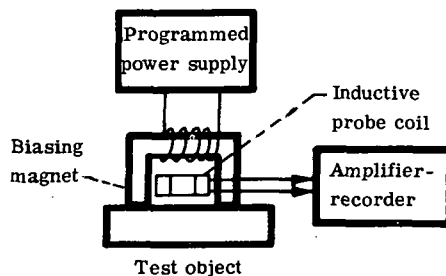
Nuclear Magnetic Resonance

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Specimen is immersed in static magnetic field. Radiofrequency excitation is applied to specimen to induce nuclear spin resonances characteristic of lattice structure and local strain.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Radiofrequency excitation in static magnetic field Absorption of energy by nuclear spin effects Resonance and spin-echo pickup coil Spectrograph and oscilloscope display Spectrographic (requires library of spectra)
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	----- Lattice environment (of element and isotope) ----- ----- Dopants, impurities, and composition Local and/or residual strain -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals, nonmetals (including semiconductors), liquids, and gases Substrates, specimens or samples, particles and powder Experimental specimens Phase study of melts Metal powder, moisture content (of paper), and germanium or silicon semiconductors
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Close proximity to surface; specimen containment Excitation and probe coils must adapt to part or specimen Detects to order of 10 percent of elements present Restricted to surface because of "skin-effect" Material must contain nuclei with magnetic moments.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	References 19 and 20 ----- ----- ----- ----- Electron paramagnetic resonance and nuclear quadrupole resonance



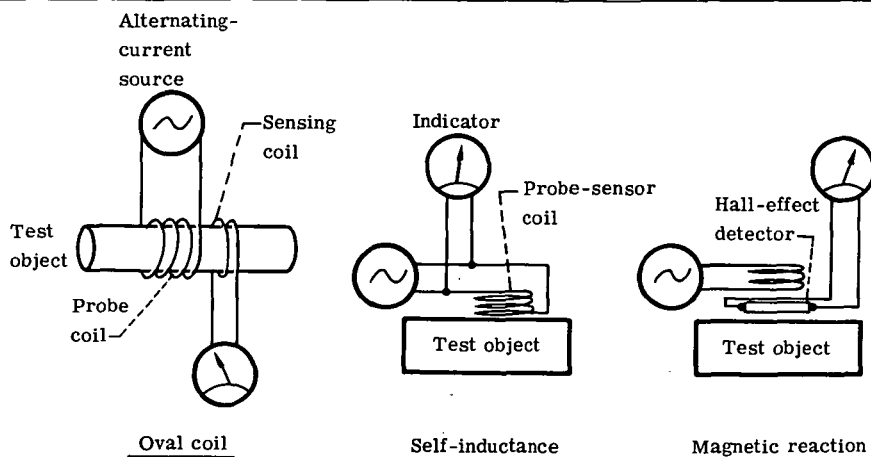
Barkhausen Effect

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Ferromagnetic material is magnetized by external field, and Barkhausen noise indicates state of residual stress. Indications derive from small abrupt increments in magnetization.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Increasing or decreasing magnetizing field Abrupt magnetization increments; Barkhausen noise Inductive loop or coil; Hall probe Oscilloscope display; coordinate plot Comparative or differential analysis; requires catalog of Barkhausen signatures for different matrixes and substrates
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Inclusions Grain size, orientation, and inhomogeneities ----- ----- ----- ----- Magnitude and direction of applied and residual stresses Stress fields accompanying plastic deformation
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Ferromagnetic materials Subsurfaces and substrates; specimens and samples ----- Diagnosing stress fields and states Compressor and turbine disks and blades, bearings, and power transmission components
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Access to surface required; contact not necessary Probe and magnetizer must accommodate part. Changes of the order of magnetic domain size Ambient noise and/or fields may mask indications. Limited to flaw location and ferromagnetic inclusions
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 16 ----- ----- Barkhausen noise -----



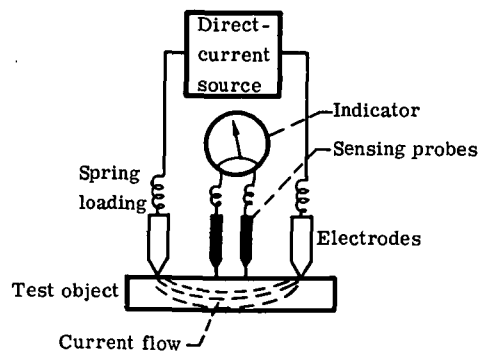
Eddy Current

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Localized alternating-current loop (eddy) is induced in test object. Inductive reactance of probe to magnetic field of induced current indicates subsurface flaws.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Localized induced current of 200-Hz to 2-MHz range Perturbation of induced current and hence induced magnetic field Inductance coil; Hall probe Meter deflection; oscilloscope trace Differential or comparative; reference standard required for each type of flaw
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Cracks, seams, pits, and inclusions ----- (Wall) thickness and coating thickness Conductivity and permeability Composition variations Heat-treatment effects -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals, alloys, and electroconductors Subsurfaces and substrates; regular and uniform shapes Feedback control for sorting materials and parts In-situ diagnosing of rotating components Tube, wire, ball bearings, nonmetal coatings, train rails and wheels, airframe components, turbine blades and disks, and automotive transmission shafts
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	No contact but close proximity of probe to surface Probe usually tailored to accommodate and fit around item Cracks to order of 0.2-millimeter length False indications possible because of mixed variables, edge effects, and lift-off (clearance) effects Low penetration (limited to thin walls or near-surface flaws)
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 2 (sections 35 to 42) Reference 7 Reference 4; ASTM E-309-71, E-243-67T, E-246-71, E-215-67, E-268-68 Magnetic reaction analysis and phase-sensitive eddy current Static magnetic field, magnetic particle, and electric current



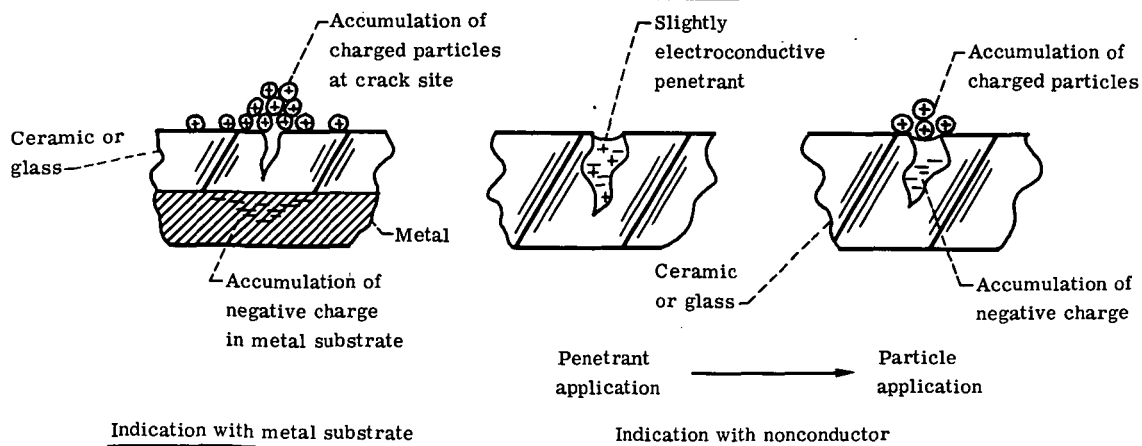
Electric Current

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Current is flowed through part or zone under test. Current strength or density between electrode pair touching surface is affected by inhomogeneities and discontinuities.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Current between pair of surface contacts or probes Voltage drop and external magnetic field perturbation Potential probes, Hall probe, or induction coil Potentiometer indication; oscillograph Comparative; requires standard flaws and calibration curves
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Cracks and inclusions Segregations and grain orientation Thickness variations Resistivity, conductivity, and stress or cold-work ----- Corrosion, erosion, wear effects, fatigue damage, and crack propagation
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metallic materials and electroconductors Surfaces and substrates; uniform, regular areas and shapes ----- Railroad track scanning ----- Bars, plate, rails, fastenings, and joints; pressure vessels, tanks, and hulls
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Good surface contact required Electrode or probe spacing and contact critical Can indicate (relative) depth of cracks Dependent upon shape and orientation of discontinuity ----- Edge-effects and contamination of surface limit utility; may mar surface
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 2 (section 35) ----- ----- Electric current injection Static magnetic field and eddy current



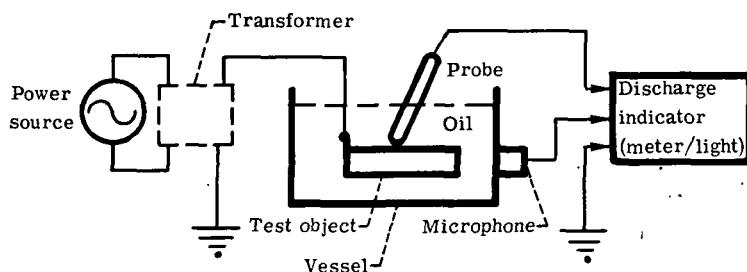
Electrified Particle

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Electrified powder is sprayed on surface. Attracted by electrostatic charge distribution at surface cracks, electrified powder accumulates at edge of cracks.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Spray of triboelectrified powder (usually CaCO_3) Accumulation of particles drawn to edge of crack Visual examination for accumulations Side illumination and photographic recording Direct indication; dependent on particle size and shape, gas (air) supply, and humidity control
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Cracks, pinholes, and crazing ----- ----- ----- ----- Crack growth characteristics -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Electrically nonconducting materials Surfaces and coatings ----- ----- Porcelain enamel; enamel, plastic, and paint coatings; glass-to-metal seals; metal-backed dielectric materials; brittle coating stress cracks; ceramics
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Surface must be carefully cleaned and dried. Flaw must be surface connected Cracks to order of 0.1 micrometer wide False indications caused by high humidity, moisture streaks, lint, and improper cleaning and/or drying Poor resolution on thin coatings; high-voltage discharge but slight shock
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 2 (sections 28 and 29) ----- ----- Triboelectrified powder Filtered particles



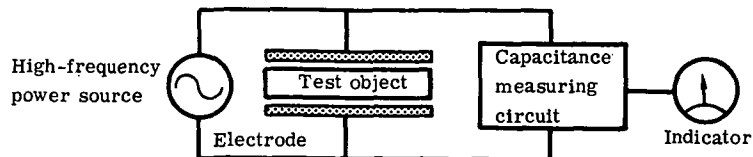
Corona Discharge

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Field of intense ionization and discharge is produced by high-voltage probe touching part near flaw. Gas and vapor trapped in cracks and voids is ionized and detected.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Applied voltage field (usually alternating voltage) Current pulse, radiofrequency radiation and/or static, audible sound, and sparks Visual, microphone, and electrometer Meter deflection, neon flash, and audio signal Direct; can be calibrated to indicate gas volume contained in discontinuity
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Cracks, voids, debonds, and delaminations ----- ----- ----- ----- ----- -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Nonmetallic and dielectric materials Surfaces and substrates; range of shapes and sizes Process residue and/or contamination ----- Solvent or liquid penetrant contamination of parts. Electrical wiring, reinforced plastics, filament-wound structures, and laminated structures.
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Access to surface required Polished probe and grounding fixture for part needed; probe shape critical Rough indication of crack or void size Cracks must be surface connected. Part should be amenable to oil immersion for most applications. Electric discharge.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	References 21 and 22 ----- Reference 4; ASTM D-1868 Spark discharge Tesla coil test



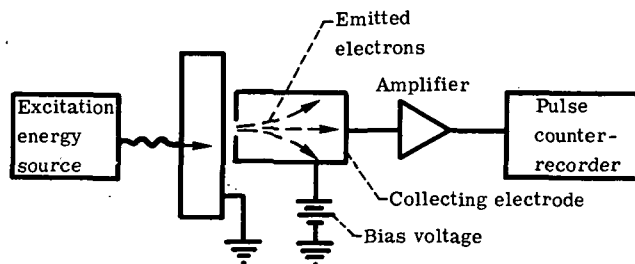
Dielectric

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Displacement of electric charge is induced in part under test. Dielectric properties and/or anomalies are indicated by capacitance and/or polarization effects.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Application of high-frequency electromagnetic field Magnitude and variation of induced displacement current Capacitance bridge Meter deflection Comparative or differential; requires reference part, material, or standard
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Pinholes, porosity, and leaks ----- Thickness Dielectric constant and dissipation factor Moisture content and degree of cure High-frequency power-factor and/or breakdown -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Electroinsulators and dielectrics Surfaces and substrates; plate and sheet forms ----- ----- Phenolic and glass-epoxy structures, electrical insulators, sheets and films of resin, paper, and glass
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Access to only one surface required at close proximity Probe geometry variable Pinhole-size flaws Ambiguous response to mixed variables Applies best to thin materials
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 23 ----- ----- ----- Corona discharge and microwave



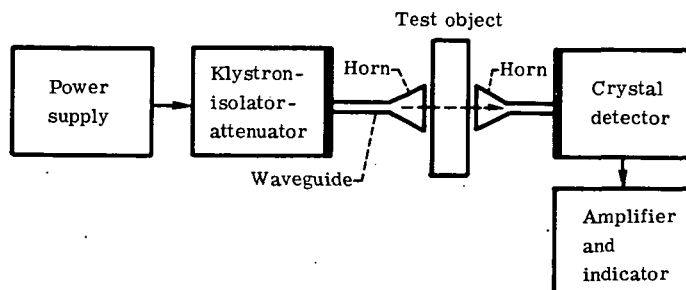
Exo-electron Emission

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Specimen surface is stimulated to emit electrons. Rate of electron emission varies with work function, which varies in turn with surface state and fatigue.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Ultraviolet and/or thermal radiation and ultrasonic vibration Variation of exo-electron current Collecting electrode Electrometer indication; counter and integrator Comparative or differential; becomes quantitative with reference standard and calibration
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	----- ----- ----- ----- Surface contamination Fatigue damage and life -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals Surfaces and substrates; uniform and regular surfaces ----- ----- Metallurgical specimens (steel, aluminum, and titanium)
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Close access to surface required; no surface films Probe configuration must accommodate part or surface geometry and methods of excitation Sensitive to order of 1 percent variation of fatigue life Ambiguous response from humidity and/or contamination of surface Experimental technique
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 24 ----- ----- ----- -----



Microwave Radiation

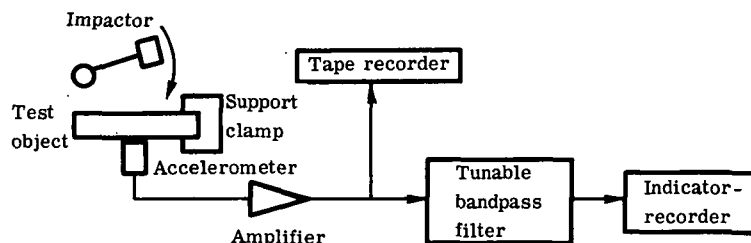
METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Continuous or modulated microwave radiation directed at object propagates according to internal state or structure of part.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Electromagnetic radiation of 3- to 0.03-centimeter wavelength Scatter, reflection, and/or attenuation of radiation Microwave guide and crystal detector Meter deflection; coordinate plot Comparative, phase-amplitude differentiation; reference standard required
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Cracks, porosity, holes, and debonds Inhomogeneity Thickness and position Dielectric properties Compositional variations, moisture content, and cure Vibrational characteristics
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Plastic, cellulose, ceramic, liquid, and elastomer Surface, bulk material, and coatings Feedback control of thickness and/or position ----- Reinforced plastic structures, polyurethane foam, solid (rocket) propellant, and motor cases
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	No surface contact is required, but positioning of part may be critical. Alinement and coupling of waveguide and detector is critical; complex waveguide arrangement usual Thickness variations to order of 25 micrometers Spatial resolution for flaws depends on probe (horn) size. Requires metal backing for thickness and position gaging of nonmetals; no microwave hazard at power levels usually used
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 25 (ch. 13) ----- ----- ----- Dielectric and corona discharge



SONIC-ULTRASONIC TECHNIQUES

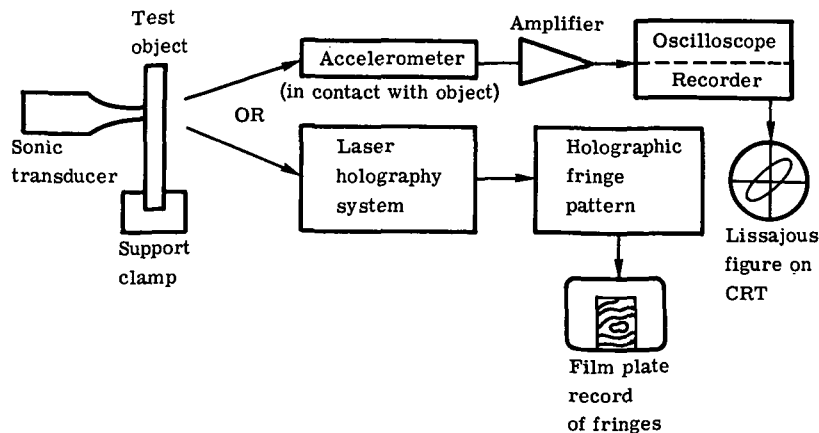
Acoustic-Impact

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Tapping or ringing of object is accomplished by striking it. Mechanically applied pulse causes response vibrations indicative of anomalies and/or flaws.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Impact energy from hammer or pulser Vibrational response and acoustic damping Ear, microphone, and/or accelerometer Audible sound, meter deflection, and oscilloscope trace Comparative; based on sonic signature vibrational and/or dampening response identification
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Cracks, debonds, and delaminations Macrostructural variations and anomalies Variations of physical dimensions Density, mass, and elastic properties ----- Differential dynamic response and damping capacity -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals, nonmetals, and composites Entire objects, including complex shapes Off-line component testing Integrity of fasteners, bonds, and cores Honeycomb, laminated, brazed, and adhesive-bonded structures; bolted or riveted assemblies, and automotive components
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Contact, fixturing, and support of object required Pulser design and impact point critical Low spatial resolution to order of centimeters Sensitive to ambient and extraneous noise and signals Mass and/or complexity and impact point influence results. All physical and geometric properties but the one tested must be constant.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	References 2 (section 51) and 26 ----- ----- Impact, shock, tapping, and ringing tests -----



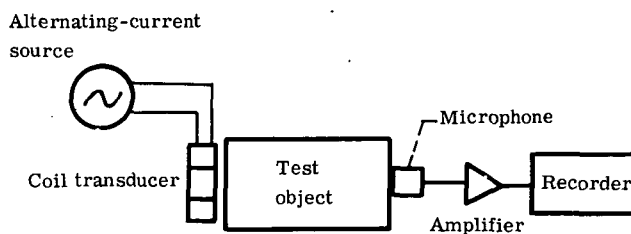
Sonic Vibration

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Continuous sonic vibrations are imparted to object. Induced natural-frequency vibrations of test object reveal flaws and physical property variations.
	PROBE MEDIUM AND/OR ENERGY SOURCE	Periodic force applied by exciter or transducer
	NATURE OF SIGNAL AND/OR SIGNATURE	Resonance and/or harmonic response in 0- to 20-kHz range
	DETECTION AND/OR SENSING METHOD	Microphone and accelerometer or holographic interferometry
	INDICATION AND/OR RECORDING METHOD	Meter deflection; oscilloscope or holograph
	INTERPRETATION BASIS	Comparative; frequency-spectrum, Lissajous-pattern or holographic fringe-pattern identification
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS	Debonds, delaminations, and cracks
	STRUCTURE OR MALSTRUCTURE	Metallurgical variations
	DIMENSIONS AND METROLOGY	Variations in physical dimensions
	PHYSICAL AND MECHANICAL PROPERTIES	Density, elasticity and shear moduli, and Poisson's ratio
	COMPOSITION AND CHEMICAL ANALYSES	-----
	STRESS AND DYNAMIC RESPONSES	Differential dynamic response and/or damping capacity
APPLICATIONS	SIGNATURE ANALYSIS	-----
	MATERIALS TO WHICH APPLIED	Metals, nonmetals, and composites
	FEATURES AND FORMS TO WHICH APPLIED	Entire objects; uniform and regular shapes
	PROCESS CONTROL APPLICATIONS	-----
	IN SITU AND DIAGNOSTIC APPLICATIONS	-----
	EXAMPLE STRUCTURES AND COMPONENTS	Solid bars, rods, and disks; abrasive wheels and rods; turbine blade and disks
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION	Contact, isolation, and support of object required
	PROBE AND OBJECT LIMITS	Pulser and probe design to accommodate part
	SENSITIVITY AND/OR RESOLUTION	Spatial resolution to order of 1 millimeter
	INTERPRETATION LIMITS	Flaw shape and location generally not revealed
	OTHER CONDITIONS AND LIMITS	Object should have definitive vibration modes. Influenced by mass and geometry of object.
REFERENCES	PRIMARY SOURCE MATERIAL	References 2 (section 51) and 27
	BIBLIOGRAPHICAL MATERIAL	-----
	STANDARDS AND SPECIFICATIONS	-----
	RELATED TERMS	Vibration, natural-frequency, and resonance tests
	RELATED TECHNIQUES	-----



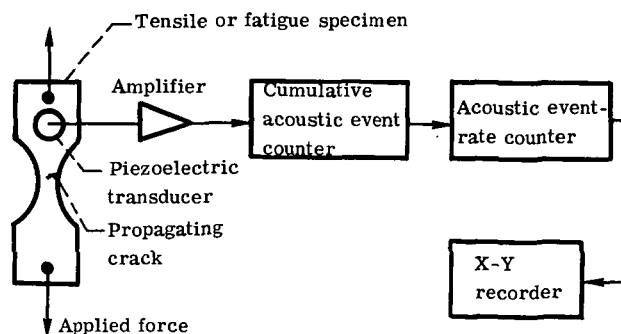
Eddy Sonic Vibration

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Mechanical or sonic vibration is induced in test object by electromagnetic coupling with transducer. Resultant sonic emissions are indicative of flaws.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Eddy currents induced in test object Sonic resonance or chatter characteristic of object Microphone, piezoelectric transducer, and accelerometer Audio and/or oscilloscope trace or pattern Comparative; sonic signature and/or vibration and resonance pattern identification
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Debonds and delaminations Malstructure, poor fit, misalignment, and/or loose parts ----- ----- ----- ----- -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals and nonconductors joined to metals Entire objects and structures; regular and uniform shapes ----- ----- Laminations, bonded metal surfaces, adhesive bonds, and boron-graphite composite structures, metal-faced or metal-core honeycombs
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Close contact with surface required Probe should fit or accommodate part Relatively coarse indication of flaw presence Ambiguous response to mixed variables Part must contain electroconductor component for coupling with transducer.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	References 28 and 29 ----- ----- ----- Sonic vibration



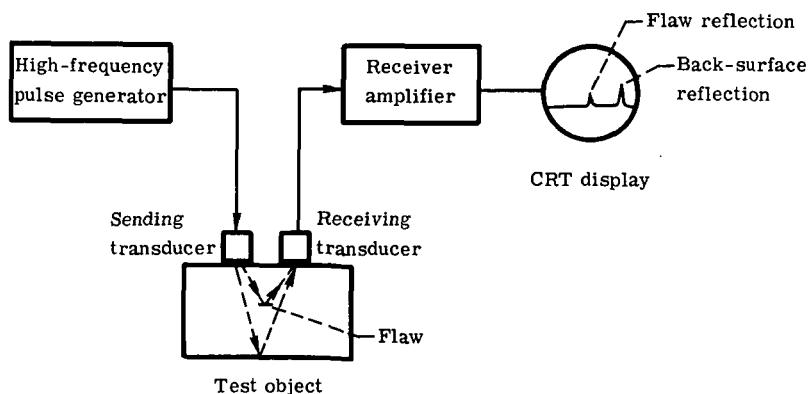
Acoustic Emission

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Phonon signals arise from plastic deformation or fracture. Ultrasonic emission rate and intensity reveals crack initiation and propagation and deformations activated by stressing.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Energy released at deformation or fracture sites Stress or ultrasonic waves propagating in material Piezoelectric transducer Digital counter, meter indication, and coordinate plot Comparative or differential; analysis of emission count rate, amplitude-frequency spectrum, and differential signal arrival time
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES	----- ----- ----- Tensile and fatigue properties ----- Crack initiation and propagation; strain rate; friction, wear, spalling, and erosion effects; martensitic phase transformation; stress corrosion; and fatigue
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals, nonmetals, and composites Welds, coatings, bonds, substrates, and entire objects Welding and die-forming; pressure (proof) testing Incipient failure detection in stressed structures; dynamic monitoring Fracture specimens; nuclear, cryogenic, and pressure vessels; aircraft engine components; and fluid systems
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Contact, acoustic coupling, and stressing required Probe coupling, waveguides, and arrangement critical Sensitivity to crack precursors and microcracking under investigation Multiple probe and computer for flaw location by triangulation required Poor acoustic channels, noise, temperature effects may hamper effective signal extraction. High ductile materials yield poor signals. Requires creation of signature catalog for signal interpretation.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	References 30 and 31 ----- ----- Stress wave emission Acoustic impact and sonic vibration



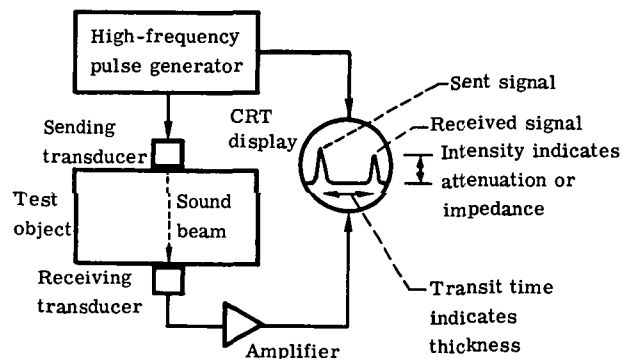
Pulse-Echo Ultrasonics

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Ultrasonic pulses are directed into test object. Ultrasonic echos and reflections indicate presence, absence, and location of flaws, interfaces, and/or discontinuities.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Beam of pulsed ultrasound, 20 kHz to 50 MHz in range Reflection or transmission of pulses or echos Piezoelectric transducer(s) Oscilloscope trace and pulse-echo gating Quantitative for flaw and interface location; reference standards required for calibration and flaw characterization
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Cracks, voids, laminations, inclusions, and debonds Porosity; metallurgical structure and graininess Thickness Density and sonic velocity ----- Crack growth -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals, nonmetals, and composites Substrates, joints and bonds, structure components Heat treatment, grinding, and joining and crack monitoring and control Rolling mill process control and monitoring Sheet, plate, bar, and tube stock; castings; forgings; welds; airframe and engine components; pressure vessels; and nuclear reactor components
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Access to one side and liquid coupling to object Special probes, coupling, and alinement fixtures usual Flaws to order of 0.01 millimeter in size Ambiguous signals may arise as a result of scatter effects, multiple reflections, and geometric complexity. Small or thin parts are difficult to inspect.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	References 2 (sections 43, 48, and 49) and 32 References 33 and 34 Reference 4; ASTM E-164-65, E-317-68, E-127-64 ----- Transmission, resonance, surface-wave, critical-angle, delta, contact, and immersion ultrasonics



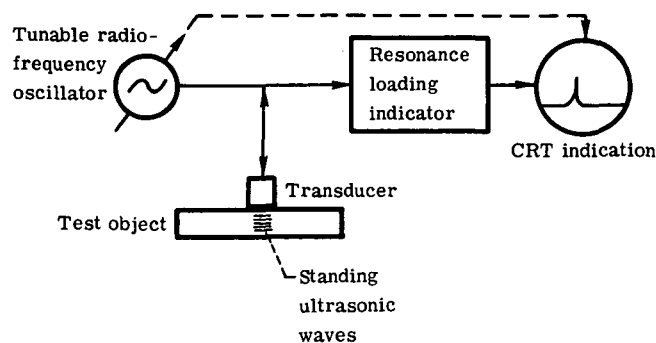
Transmission Ultrasonics

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Continuous, pulsed, or modulated ultrasound transmitted through part is attenuated by flaws and/or interfaces.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Beam of ultrasound (usually 20-kHz to 50-MHz range) Attenuation or obstruction of ultrasound Piezoelectric transducer Meter deflection; oscilloscope trace Comparative or differential; reference standards required for quantitative indications
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Cracks, voids, laminations, and inclusions ----- Thickness Density, impedance, and sonic velocity ----- ----- -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN-SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals, nonmetals, and composites Uniform, regular, and/or flat parts ----- ----- Sheet, plate, and bar stock; laminated structures
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Coupling and access to two sides Selection, alinement, and fixturing of probes Flaws to order of 0.2 millimeter Spurious signals may arise as a result of reflections, dispersion, or resonance. Poor results unless surfaces are uniform and parallel and only one type of defect is present.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 2 (sections 43 and 49) and 32 References 33 and 34 ----- ----- Pulse-echo, surface-wave, critical-angle, contact, immersion, and delta ultrasonics



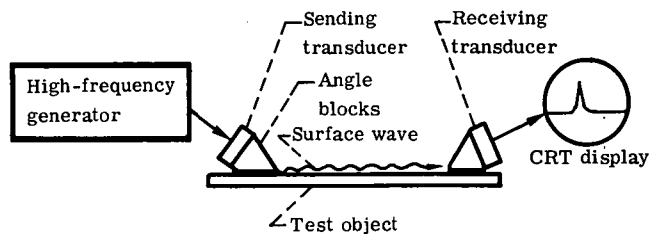
Resonance Ultrasonics

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Frequency is varied until probe introduces continuous and compressional ultrasonic waves into part at resonant frequencies for thickness gaging.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Continuous-wave ultrasound (20-kHz to 25-MHz range) Generation of standing waves and resonance Piezoelectric transducer Meter indication; oscilloscope trace Quantitative; requires catalog of sonic velocities and/or dimensions for thickness and/or velocity measurements
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Delaminations and debonds Matrix structure variations Thickness Velocity of sound ----- ----- -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Homogeneous metals and nonmetals Platelike forms, tubelike forms, and uniform parts ----- Blistering, thinning, and corrosion of pipelines ----- Extruded, drawn, or bored tubes; rolled or milled sheetmetal; pressure vessels; ship hulls; boiler tubes; and glass, ceramic, and rigid-plastic parts
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Smooth surface and close coupling preferred Frequency, type, and mounting of transducer critical Thickness variation to order of 0.1 percent Spurious indications may arise as a result of extraneous vibrational modes, harmonics, end effects, and/or reflections Taper or irregularities reduce signal value
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 2 (sections 43 and 50) and 32 References 33 and 34 Reference 4; ASTM E-133-67 ----- Pulse-echo, transmission, surface-wave, critical-angle, delta, contact, and immersion ultrasonics



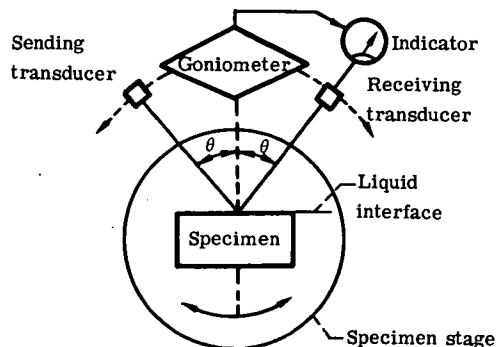
Surface-Wave Ultrasonics

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Ultrasound is introduced into part at specific angle. Waves are totally reflected inside part and travel over the surface to detect surface and surface-connected flaws.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Continuous or pulsed ultrasound to MHz levels Attenuation, damping, or velocity change Piezoelectric transducer Oscilloscope trace Comparative or differential
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Cracks Roughness, scratches, and graininess Thickness variation and eccentricity ----- ----- Incipient cracking -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Light metals and alloys Surfaces and subsurfaces; smooth and/or uniform shapes High-quality sheetmetal process monitoring ----- Aluminum plates and sheets, steel plates and sheets, machine parts, rolled or extruded pieces, and turbine blades
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Contact or coupling with surface Special angle blocks or wedges required for probe Minute surface cracks to order of 0.1 millimeter deep Very sensitive to surface roughness Surface waves can be dampened by water, oil, dirt, and/or fingerprints.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	References 2 (section 45) and 35 Reference 34 ----- Rayleigh wave ultrasonics Lamb wave ultrasonics



Critical-Angle Ultrasonics

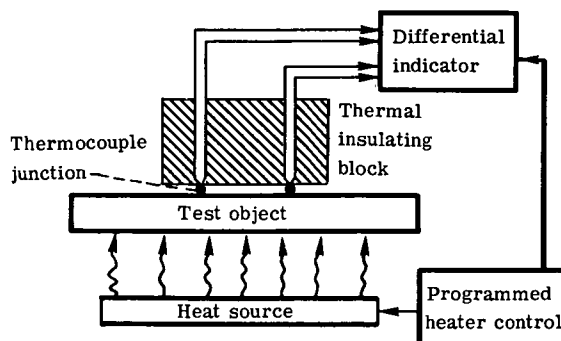
METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Ultrasonic beam is reflected from test surface. Angle of incidence is varied and reflected ultrasound intensity passes through a minimum for an angle that varies with surface and/or substrate properties.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Ultrasound beam at 15 MHz or greater Intensity variation with beam angle of incidence Piezoelectric transducer Goniometer, meter indication, and oscilloscope trace Comparative or differential; calibration or reference standard required
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	----- Roughness and grain orientation ----- Elastic moduli and sonic velocity ----- Cold-work, heat-treatment, and annealing effects -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals Surfaces and substrates; coatings and films ----- ----- Metallurgical specimens and irradiated reactor materials (steels)
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Liquid coupling to surface by immersion Special staging of part and probe for goniometry Sensitivity under investigation Ambiguous response from beam spread; side-lobe effects and beam shift. Not useful with complex or very small specimens; experimental technique
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	References 26 (ch. 4), 36, and 37 ----- ----- Reflection ultrasonics Pulse-echo, transmission, resonance, surface-wave, delta, contact, and immersion ultrasonics



THERMAL TECHNIQUES

Contact Thermometry

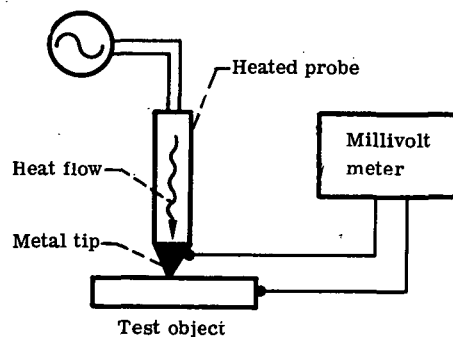
METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND-BASIC RESULT	Measurement of temperature and heat flow variations through test object indicates thermal properties and/or anomalies.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Heat flow Temperature variation Thermocouple, thermistor, and/or thermal comparator; thermosensitive layer Meter deflection; thermal image Comparative or differential; quantitative reading based on calibration with reference specimen or object
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	----- Roughness Thickness Thermal time-constant and/or conductivity ----- Case hardening -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals and nonmetals (ceramics, mica, quartz, glass) Surfaces, subsurfaces, and bulk; uniform and simple shapes Materials sorting Implanted in electrical motors and generators Experimental specimens; electrical components and equipment
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Contact and attachment to part May require built-in probes or permanent attachment Subject to errors in true temperature response Sensitive to ambient temperatures, object size and geometry, surface roughness and condition -----
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	References 39 and 40 Reference 38 ASTM E-235-67, E-220-72, E-230-72 (ref. 4). ----- -----



Thermoelectric Probe

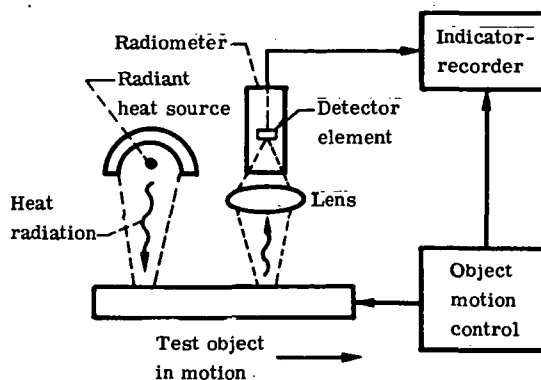
METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Voltage produced at probe-part contact point due to thermal gradient indicates variations in surface and/or substrate composition.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Thermal gradient produced by heated probe Characteristic bimetallic Seebeck voltage Potentiometric circuit containing part and substrate Potentiometer Comparative or differential; reference or standard surface required for calibration
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Porosity Segregations and depletions Thickness variations Thermoelectric properties Surface chemistry and composition ----- -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals and electroconductive substrates Subsurfaces and substrates; coatings Metal sorting and coating thickness ----- Diffusion coatings and layers, ceramic-coated metals, P-N junctions in semiconductors, and graphite parts
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Uncontaminated surface and tight contact required Probe tip material, hardness, and oxidation critical Voltages in individual metal grains sensed Contact pressure variations and probe radius variation and dulling limit utility. Primarily experimental technique
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	References 41 and 42 Reference 38 ----- ----- Thermochromic, infrared radiometry, electrolytic probe, and eddy current

Heater power source



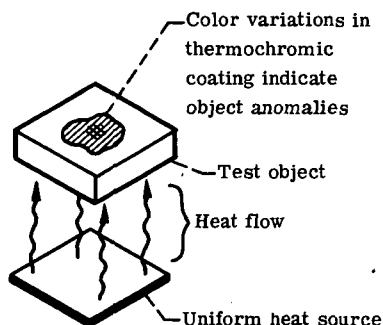
Infrared Radiometry

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Thermal radiation from a heated surface is measured. Active or ambient heating of object reveals heat flow anomalies caused by structure properties and flaws.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Heat injection by radiation, conduction, and/or ohmic heating Perturbation or impedance of heat-flow pattern Radiometer; infrared detector and scanner Meter deflection; thermal pattern and profile Differential or absolute temperature measurement
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Lack of bond, imbedded material, voids, and porosity ----- Thickness variations Emissivity, reflectivity, and temperature ----- Heat-transfer characteristics and fatigue cracking Isotherms and hot spots
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	All materials (but usually best for metals) Surfaces, substrates, substructures, and bulk parts Feedback control of welding processes Heat leaks, degradation and corrosion effects, dynamic monitoring of structures Spot welds, coating and plating thickness, adhesive and braze bonds, solar cells, pipe and pressure vessel welds, solid-propellant motor-case bonds, electric and electronic components
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	No contact; emissivity coatings may be required. Fixturing for heating and cooling required; orthogonal view of surface preferred Temperature variations to order of 1°C Poor resolution of flaw area with thick specimens Locates flaw areas; no indication of nature of flaw
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	References 25 (ch. 14) and 43 Reference 38 ----- ----- Thermochromic and thermography



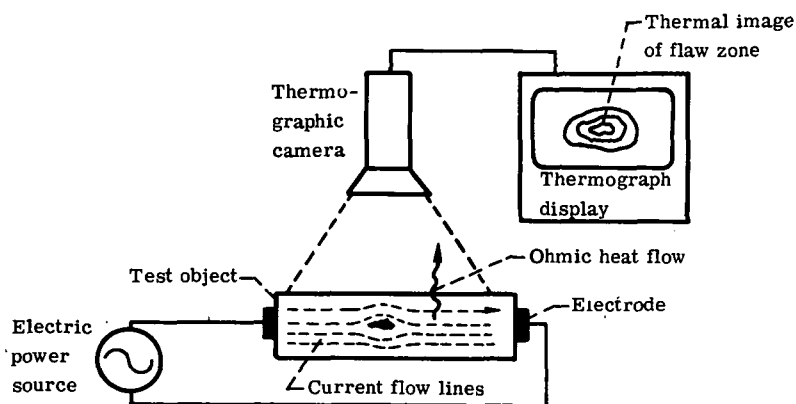
Thermochromic

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Coating of thermosensitive substance is applied to surface. Variations in color reveal anomalies and/or perturbations of heat flow and/or temperature in substrate or bulk.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Application of heat Pattern of color variations of coating Thermochromic paint and liquid crystals Direct visual and photographic observation Differential, pattern analysis; reference standard required
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Cracks and lack of bond Heat leads, hot spots, and poor contact Thickness variations ----- ----- Heat-transfer characteristics and isotherms -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals, nonmetals, and composites Surfaces and substrates; uniform shapes ----- Dynamic monitoring of temperature variations Craze and adhesive joints, metallic platings and coatings, crushed core in honeycomb structures, blockage in coolant passages, electrical assemblies, and glass cloth composites
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Surface access required for cleaning and coating Fixturing for proper heating of test object Temperature differences to order of 0.1°C Critical time-temperature relation Effective temperature range: 0° to 150°C . Image retentivity affected by humidity. Best with thin-walled structures and nonmetal laminates.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	References 44 and 45 Reference 38 ----- Thermosensitive paint and cholesteric crystals Infrared radiometry and thermography



Electrothermal

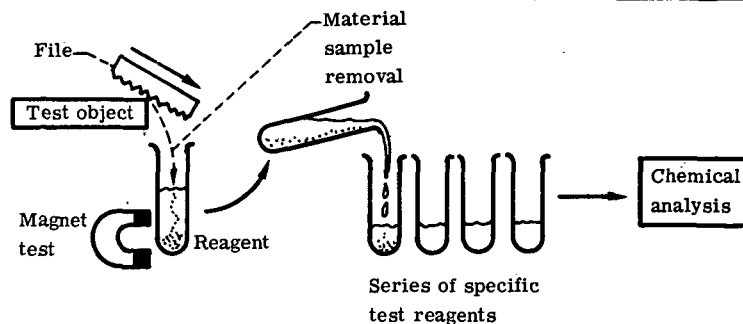
METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Electric current flowing in part generates heat flow that in turn produces surface-temperature variations and/or anomalies indicative of internal flaws.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Ohmic heating by electric current Surface-temperature distribution and pattern Thermosensitive coatings and infrared radiometry Thermometric indication and thermal imaging Comparative or differential; thermal mapping
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Voids, cracks, and inclusions ----- ----- ----- ----- ----- -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals and electroconducting substrates Surfaces and subsurfaces; regular and uniform shapes ----- ----- Welds, machined parts, plate and sheet materials, turbine blades, and engine components
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Visual access to surface and electrode contact required Electrode contact and spacing tailored to part Cracks to order of 0.03 millimeter Requires combination with other thermal techniques for flaw detection Part should be uniform in region of interest. Sensitivity to thickness variations.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 46 ----- ----- ----- Infrared radiometry, thermography, and thermochromic



CHEMICAL-ANALYTICAL TECHNIQUES

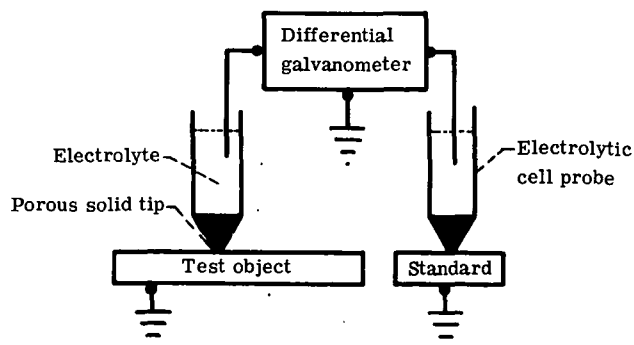
Chemical Spot Test

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Small sample of material is removed from test object to determine its composition. Chemical identifications are made by combining specimen particles with series of reagents.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Chemical reaction Color and/or phase boundary changes; precipitation Visual Direct observation Qualitative analysis; standardized procedure for reagent preparation and application sequence
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	----- ----- ----- ----- Elemental composition and alloy identification ----- -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals and alloys Surfaces and subsurfaces Applied prior to joining and fabrication operations Metallurgical specimens Stock material identification; engine components
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Requires semi-microscopic specimen particles from part Special chemical kit of prepared reagents Approximately 150 metals and alloys identified Assumes particles taken are representative of entire part Difficult to establish quantitative values of constituents detected; minute amount of material removed
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 47 ----- ----- ----- Spark test and spark oxidation



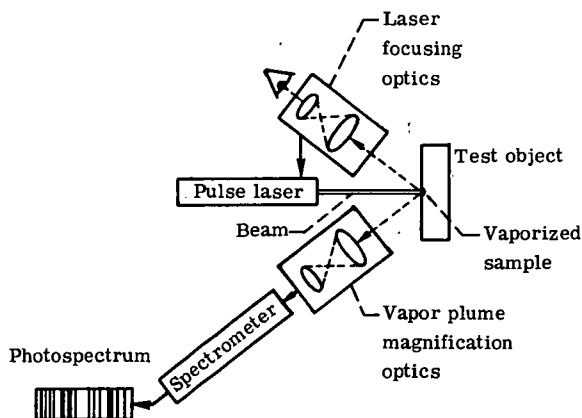
Electrolytic Probe

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Electric potential at probe contact point is used to determine surface composition. Electrolyte-saturated porous probe material produces EMF characteristic of surface anomalies.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Electrolyte-saturated probe Galvanic cell voltage generated on contact Potentiometric circuit containing part Potentiometer and galvanometer Comparative or differential; qualitative indications depend on catalog of specific chemical reactions
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Inclusions ----- ----- ----- Compositional and/or chemical variations Residual stress -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals Surfaces Spot checking ----- Tube, plate, and bar stock
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Surface access and contact required Depends on choice of electrolyte and probe material Sensitivity not established Chemical identification may be ambiguous Technique not well developed for solids
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 48 ----- ----- Electrochemical test Chemical spot test



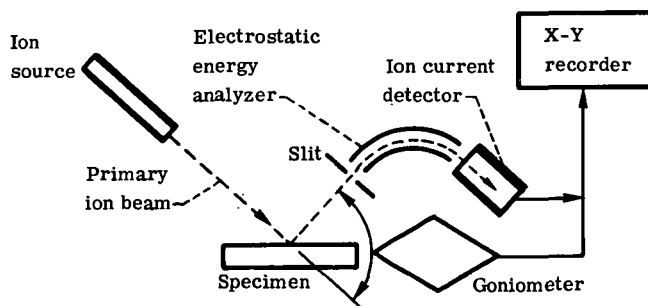
Laser Probe

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Laser beam is microfocused on test object to determine composition and/or microstructure. Minute quantities of vaporized material are spectroscopically analyzed.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Pulsed laser beam and electroexcitation Ionized vapor plume sample Spectrometer Spectrograph Differential and/or quantitative analysis
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	----- Grain and/or microstructure; inclusion, grain, grain-boundary analysis ----- ----- Analysis and distribution of elements and impurities ----- -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals, nonmetals, and composites Surfaces, subsurfaces, layers, deposits, and coatings ----- Metallurgical specimens and mineral analysis Aircraft engine components, jet rotor hubs, and experimental specimens
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Optical view and access to surface required Focusing and microminiaturization of beam diameter Analytical accuracy to order of 5 percent Depends on control and reproducibility of laser beam diameter and energy Minute amount of material removed
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	References 49 to 51 ----- ----- Laser microprobe Ion probe, ion scatter, and chemical spot test



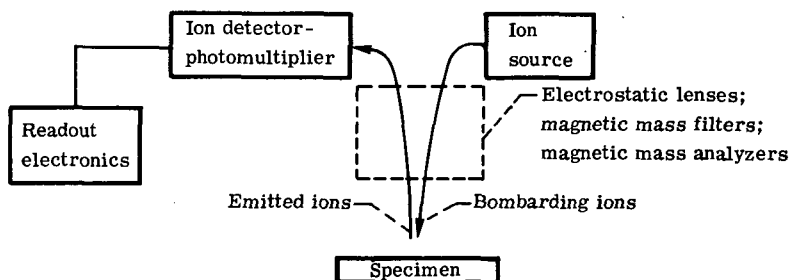
Ion Scatter

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Surface monolayer is bombarded with ion beam to determine chemical composition. Energies of scattered ions are analyzed to identify elemental composition of surface layers.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Monoenergetic beam of noble gas ions Energies of scattered ions altered by surface atoms Ion-current collector and analyzer Cathode-ray-tube display; coordinate plot Semiquantitative and/or differential; depends on catalog of energies of scatter-ion species
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	----- ----- ----- ----- Analysis, distribution, and profile of elements and impurities ----- -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metal, nonmetals, and composites Surfaces, layers, deposits, and coatings Monitoring of surface contamination and/or chemical cleaning Segregation, diffusion, oxidation, and doping studies Insulating layers, electrical relay contacts, steel tubes, and laser-glass (window)
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Part must be placed in vacuum enclosure. Only small specimens and areas can be accommodated. Composition variations to order of 100 ppm Atomic weights less than that of probe gas are not detected. Material or surface layer must have low vapor pressure.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 52 ----- ----- Ion scattering spectrometry Ion probe, laser probe, and Auger analysis



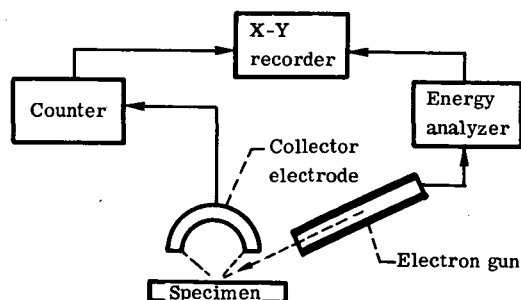
Ion Probe

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Specimen surface atoms are bombarded and ionized to determine chemical composition. Specimen ions are electrostatically impelled through mass analyzer and ion detector.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Positive or negative ion beam (up to about 25 keV) Secondary ions emitted from spot on surface Mass spectrometer and analyzer; ion imager Cathode-ray-tube display; coordinate plot Spectrographic; semiquantitative; requires library of spectra from standard or reference matrixes
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	----- Crystalline structure ----- Surface physics Analysis, distribution, and profile of chemicals, elements, and impurities ----- -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Any solid (with low vapor pressure) Surface, substrates, layers, deposits, and coatings ----- ----- Metallurgical specimens, thin films, catalysts, lubricants, and microcircuits
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Insertion of specimen into vacuum enclosure required Only small specimens or areas can be accommodated. Sensitive to order of ppm level Applied to small areas from 1 to 500 micrometers in diameter Sensitivity depends on atomic species involved; minute amount of material must be removed.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	References 53 and 54 ----- ----- Ion microprobe Laser probe, ion scatter, and Auger analysis



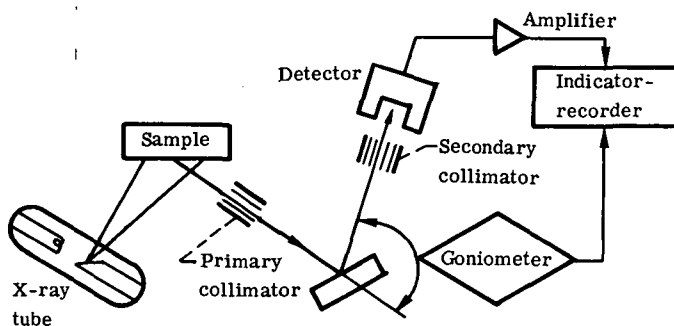
Auger Analysis

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Specimen surface is bombarded with electrons to determine chemical composition. Orbital electrons are excited and emitted with energies characteristic of atoms present in surface layers.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Low-energy electron beam (2- to 3-keV range) Emission of Auger electrons and X-rays Collector, counter, and energy analyzer Cathode-ray-tube display; coordinate plot Qualitative; spectroanalysis; requires standard spectra relative to various substrates
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	----- ----- ----- ----- Analysis of chemicals, impurities, and segregations Contamination, corrosion, and diffusion effects; embrittlement and temper -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals, alloys, and semiconductors Surfaces, films, and substrates ----- ----- Metallurgical specimens, polycrystalline and single-crystal specimens, thin films, and thermionic materials
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Prepared specimen insertion in vacuum enclosure Only small specimens and areas can be accommodated. Maximum sensitivity to order of 100 ppm Penetration depth limit of about 15 angstroms Materials must have low vapor pressures; poor resolution of adjacent atomic numbers.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	References 55 and 56 ----- ----- Auger electron emission Ion probe, laser probe, ion scatter, charged-particle activation, and X-ray fluorescence



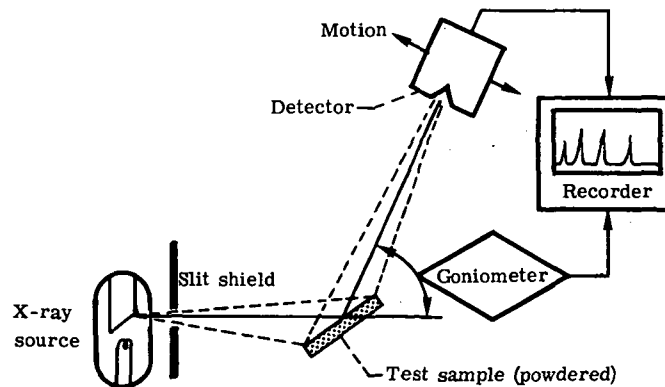
X-Ray Fluorescence

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	X-radiation of specimen surface produces fluorescence, and spectrographic scanning of emissions identifies elemental composition.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	X-radiation to 100-kV level Secondary radiation or fluorescence Crystal analyzer, scintillation, and ionization counter Coordinate plotter Quantitative spectrographic analysis; based on empirical calibration curves and/or standard specimens
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	----- ----- Thickness ----- Elemental analysis and impurities Corrosion and carburization effects -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals and liquids Surfaces, subsurfaces, coatings, films, and layers ----- ----- Metallurgical specimens; raw materials; fuels; solutions; turbine casings, diffusers, and flanges; and aircraft components
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Sample or specimen surface preparation Only small specimens and areas can be accommodated. Sensitive to trace elements to order of 0.1 percent Lower atomic numbers and high sensitivity require vacuum enclosure of specimens. Radiation hazard
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	References 2 (section 17) and 57 ----- ----- ----- Auger analysis, ion probe, ion scatter, and charged-particle activation



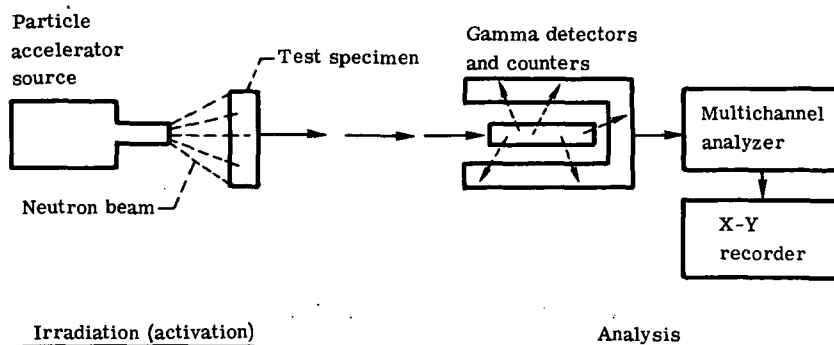
X-Ray Diffraction

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Sample of test object is exposed to X-radiation. Scatter radiation intensity varies with diffraction angles characteristic of crystalline species present.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Monochromatic X-radiation Diffraction pattern Scintillation counter and photoemulsion Diffractometric photograph and coordinate plot Analytical; differential; dependent on file of reference patterns
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	----- Crystal size, orientation, structure, and strain; lattice deformation; amorphous structure; phase changes ----- ----- Chemical reaction results Residual stress -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Crystalline materials Surface specimens (deposits and layers) ----- Manufacture of magnetic and ceramic materials ----- Electrodeposited materials, drawn wire, rolled sheet, mineral analysis, and aircraft components
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Powder samples preferred but also applicable to solid parts Special staging or containment of sample Peak-to-background ratio should be >1 to detect low-concentration constituents. Amorphous constituents may not be detected. ----- Finite crystal sizes in specimen introduce statistical errors in scintillation counting. Radiation hazard.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 2 (section 17) ----- ----- ----- -----



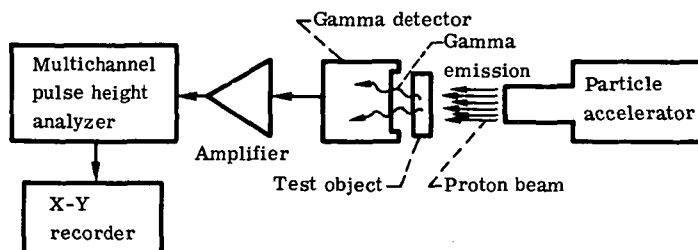
Neutron Activation

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Test object is exposed to neutron flux to determine chemical analysis. Induced radio-activity or emission characterizes and identifies elemental composition of object.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Neutron flux from reactor, accelerator, or radioisotope Characteristic gamma radiation of activated atoms Gamma spectrometer and multichannel analyzer Oscillogram, spectroplot, and/or computer printout Quantitative and spectrographic; standard or reference spectrum library required
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	----- ----- ----- ----- Elemental analysis ----- -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Indefinite range of solid and liquid materials Specimens; uniform and standard samples Off-line process sampling and control ----- Oxygen in steel, silicon in metals and ores, and biological and metallurgical specimens
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Enclosure of specimen for maximum sensitivity Special containment of part for activation Sensitive to order of ppm level of constituents Sensitivity varies directly with irradiation time. Radiation decay in object or specimen is fast.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 58 ----- ----- ----- Charged-particle activation



Charged-Particle Activation

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Beam of charged nuclei is projected at test surface to determine composition. Induced gamma emission reveals presence and abundances of elements in matrix or substrate.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Protons of lithium and other nuclei (usually to 2 MeV) Characteristic gamma emission by elements present Detector-counter and energy analyzer Cathode-ray-tube display; plot of intensity or counts against energy Quantitative; spectrographic; requires library of spectra for various matrixes
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	----- ----- Thickness Material identification Elemental analysis, elemental distribution, and profile ----- -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Indefinite range of solid materials Surfaces, substrates, and portions of entire objects ----- Early detection of corrosion and oxidation Coating thickness, alloy identification, measurement of thin films, trace element detection and laser materials
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Specimen or part is target in charged-particle beam. Beam collimation, target holder, and direct line access Sensitive from percent to order of ppm Requires knowledge of gamma yields for various matrix materials Some materials may degenerate with ion bombardment. Requires computer for data analysis and display. Radiation hazard.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	References 59 and 60 ----- ----- ----- Laser probe, Auger analysis, ion probe, ion scatter, beta scatter, neutron activation, and X-ray fluorescence



Mössbauer Analysis

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Resonance absorption or emission of gamma radiation is used to determine composition. Gamma photons penetrating substrate detect and/or respond to presence and/or distribution of tracer elements.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Gamma radiation Recoilless re-emission of gamma photons Gamma detector-counter and velocity analyzer Cathode-ray-tube display; coordinate plot Qualitative, differential spectroanalysis; requires library of reference spectra
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Homogeneity, surface gradients, and dislocations Lattice surrounding of Mössbauer nuclei Thickness Magnetic domain polarization and isomer shifts Mössbauer element detection Corrosion products -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Material containing Mössbauer elements, usually Fe ⁵⁷ Substrates, coatings, and surface films ----- Coating or substrate deterioration Fe detection, Fe film on stainless steels, retained austenite in stainless steels, and nitride surfaces on stainless steels
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Close proximity of source and detector to surface Precise (ultrasonic) vibration of source or part Requires liquid-nitrogen temperatures for some species Depends on seeding or implantation or natural presence of Mössbauer elements or isotopes in substrate Radiation hazard
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 61 ----- ----- ----- Charged-particle activation, neutron activation, backscatter radiometry, ion scatter, ion probe, and Auger analysis

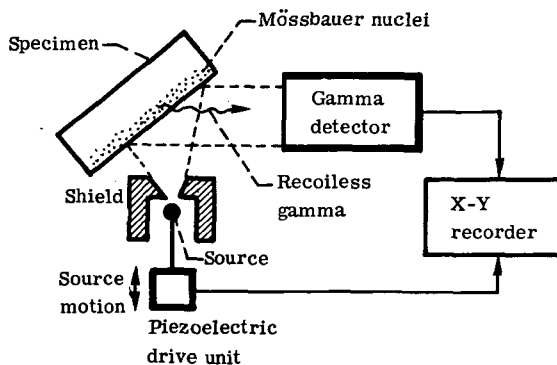


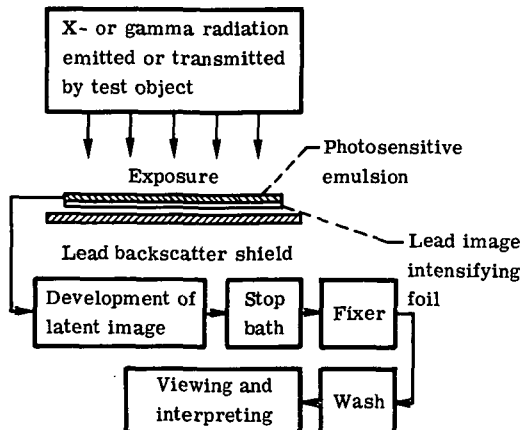
IMAGE GENERATION TECHNIQUES

Photoimaging

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	A range of methods and devices is used for optical imaging. Geometric or wave optics and special illumination are used to extract direct or derivative images of objects.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Natural, artificial, monochrome, coherent, and/or ultraviolet light Reflection, refraction, diffraction, transmission, and/or interference Eye, photocell, photoemulsion, videcon, and/or polarizer Visual image photograph and projection Direct indication, comparative, or differential; based on collection or library of standard reference images.
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Inclusions, pores, scratches, and mars Surface anomalies, imperfections, flatness, and form Thickness variations, orientation, and angle Reflectivity and index of refraction Impurities Birefringence -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals, nonmetals, and composites Surfaces and interiors (of transparent objects) ----- ----- Wide range of applications in metrology; complementary to other NDE techniques
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Visual access and contact Range of requirements: special optics Macro- to micro-optical measurements ----- -----
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 2 (sections 10 to 12) ----- ----- Photography, infrared photography, and ultraviolet imaging -----

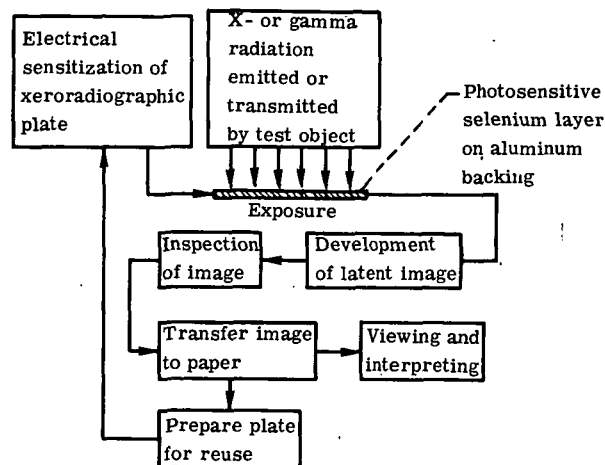
Film Radiography

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	A photographic image is produced by passage of X-rays, gamma rays, and/or electrons from or through test object onto a film. Changes produced in the film emulsion are developed to yield a radiographic transparency.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	X-rays, gamma rays, neutron activation, electrons, and photons Attenuation, transmission, or emission of radiation Photosensitive emulsion Radiographic image or transparency Direct indication, comparative, or differential; based on collection or library of standard or reference images
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Cracks, inclusions, porosity, voids, and lack of bond Misalignment and/or malstructure Thickness, diameter, position, and spacing Density ----- ----- -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals, nonmetals, and composites Range of objects and features. ----- ----- Objects of X-, gamma, neutron, and autoradiography; used to obtain neutron radiographs from activated transfer foil
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS	One-side access if autoradiography; two if external source Special filters, screens, and/or scintillators needed for image quality Resolution ranges to order of 2000 line pairs per centimeter Image quality impaired by scatter radiation and finite source or focal-spot-size gamma fogging; requires control of chemicals and photoprocessing conditions for reproducible results
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 2 (section 20) ----- ----- X-, gamma, and neutron radiography; autoradiography; xeroradiography Fluoroscopy and video radiography



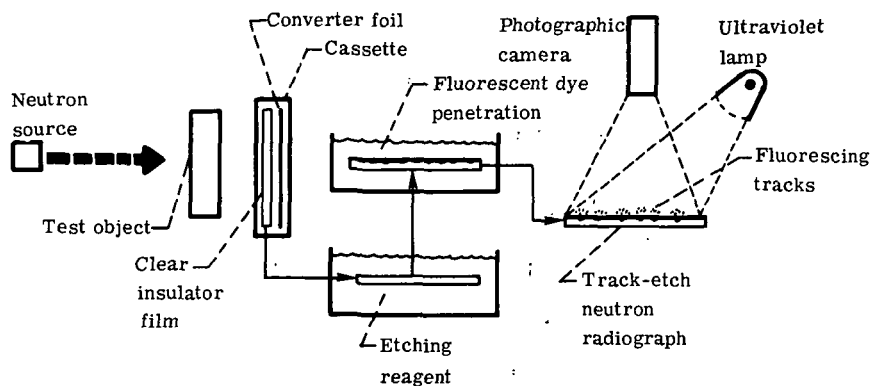
Xeroradiography

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	An electrostatic image is produced by passage of X- or gamma rays through a test object onto a charged layer. The charge-image is transferred xerographically to form an opaque radiograph.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	X- and gamma rays Attenuation, transmission, or emission of radiation Electrically charged layer Radiographic image Direct indication, comparative, or differential; based on collection or library of standard or reference images
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Cracks, inclusions, porosity, voids, and lack of bond Misalignment and/or malstructure Thickness, diameter, position, and spacing Density variations ----- ----- Edge enhancement of low-contrast images
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals, nonmetals, and composites Range of objects and features ----- ----- Objects of X- and gamma radiography
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Access to two sides of test object required Practical voltage limited to less than 100 kV Thickness sensitivity to order of 2 percent Xeroradiographic plates are easily damaged. Powder- and/or layer-deficient dots and other artifacts hamper image interpretation
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 2 (section 21) ----- ----- ----- Film radiography; fluoroscopy; X- and gamma radiography



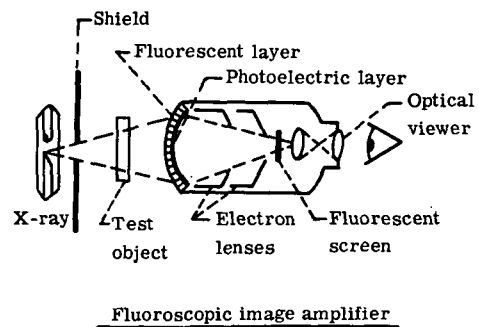
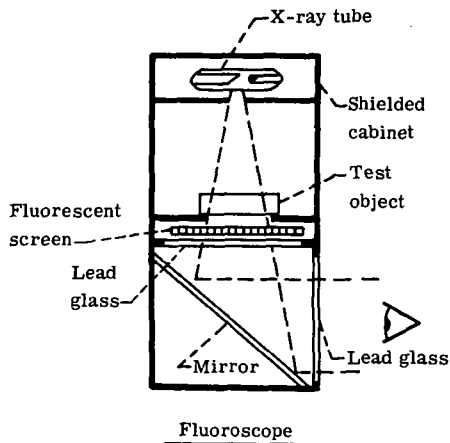
Track-Etch Radiography

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	A radiographic image is formed by neutrons passing through a test object and activating a metal foil. Ions emitted by the foil penetrate a layer of clear insulator material producing a latent image.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Neutron activation Ion-track damage of insulator material layer and film Etch-removal of damaged material and dye impregnation Radiographic image Direct indication, comparative, or differential; based on collection or library of standard or reference images
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Voids, porosity, and inclusions ----- ----- Neutron dosimetry ----- -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	----- ----- ----- ----- Objects of neutron radiography
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Access to both sides of test object required Foil transfer methods, as in neutron radiography, required Resolution to order of 0.01 millimeter Low-contrast image produced requires contrast-enhancement techniques. Experimental technique
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	References 62 and 63 ----- ----- ----- Neutron radiography



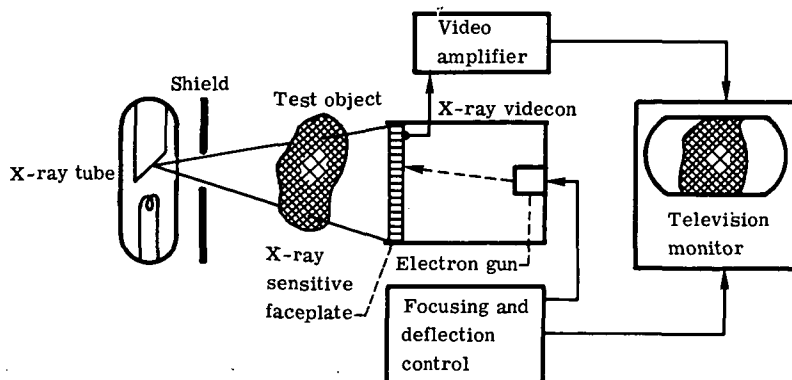
Fluoroscopy

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	A fluorescent image is produced by X-rays passing through a test object onto a fluorescent layer. An immediate and real-time image showing radiographic details appears on a screen.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	X-radiation Attenuation or transmission of radiation Fluorescent chemical layer Fluorescent image Direct indication; comparative; based on visual impressions
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Cracks, porosity, voids, and inclusions Macro-malstructure and misalignment Thickness, diameter, spacing, and position Density variations ----- Effects of distorting forces; dynamic phenomena -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals, nonmetals, and composites Range of objects and features ----- ----- Objects of X-radiography
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Access to two sides of test object required Fluoroscopic enclosure limits object size. Considerably lower resolution than film radiography Requires low ambient lighting and eye accommodation ----- Image quality hampered by screen unsharpness, attenuation by windows and mirrors, and fluorescence fluctuations
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 2 (section 19) ----- ----- ----- X-radiography and gamma radiography



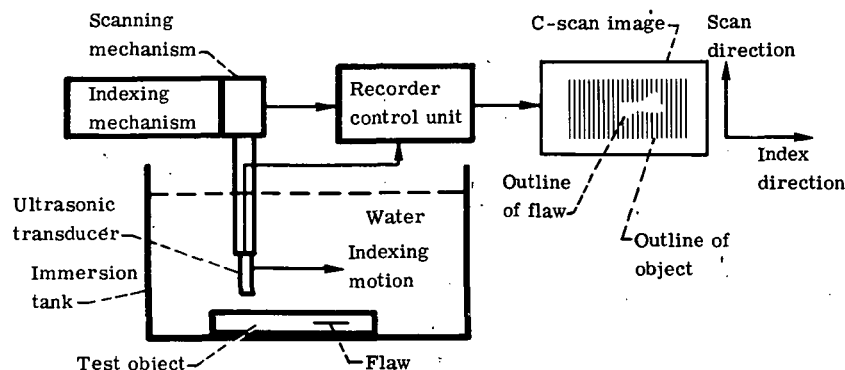
Video Radiography

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	X-, gamma-, or neutron-sensitive vidicon receives radiation transmitted through test object. Television monitor displays radiographic image.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Neutron rays, gamma rays, or X-rays Transmission or attenuation by object variables Neutron-, gamma-, or X-ray-sensitive vidicon Television display Direct observation; in-motion, real-time viewing aids interpretation of image content.
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Voids, porosity, inclusions, and cracks Malstructure and/or misalignment Dimensional variations ----- ----- Direct observation of internal motions of structure; in-motion viewing of flaws -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Indefinite range of materials Bulk materials and entire objects Real-time viewing of processing and production In-motion operation of hidden and internal components Nuclear fuel pins, casting operations, metal rolling and forming operations, liquid-metal cavitation flow patterns, and submerged welding
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Access to interpose object between source and detector Useful apertures limited to order of several centimeters Thickness variations to order of 4 percent Usually limited to coarse indication of flaws Inferior to film radiography for fine cracks
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	References 25 (ch. 8) and 64 ----- ----- ----- X-, gamma, and neutron radiography; fluoroscopy



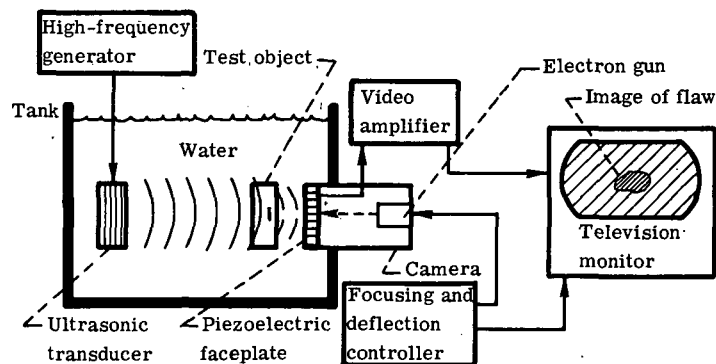
Immersion Ultrasonics

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Test object is ultrasonically scanned while immersed in liquid. Ultrasound interactions with object produce signals that are used to map or image internal flaws.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Beam of pulsed ultrasound (20-kHz to 50-MHz range). Reflection or transmission of ultrasound Piezoelectric transducer (or transducers) Oscillogram; coordinate plots and maps Comparative or differential; quantitative with reference or calibration standards
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Cracks, voids, laminations, debonds, and inclusions Porosity and segregations Thickness Density and velocity of sound ----- ----- -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals, nonmetals, and composites Subsurface, bulk, and internal features ----- ----- Sheet, plate, bar, and tube items; billets and slabs; engine components; and power transmission shafts
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Liquid immersion and access to at least one surface required Small, thin, rough-surface parts are difficult to evaluate. Discontinuities to order of 0.01 millimeter Ambiguous response from scatter and geometric complexity Geometrically complex and/or nonregular objects require intricate scanning arrangements
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 2 (sections 44 to 47) ----- Reference 4; ASTM E-214-68 B-scan and C-scan ultrasonics Ultrasonic videography and ultrasonic holography



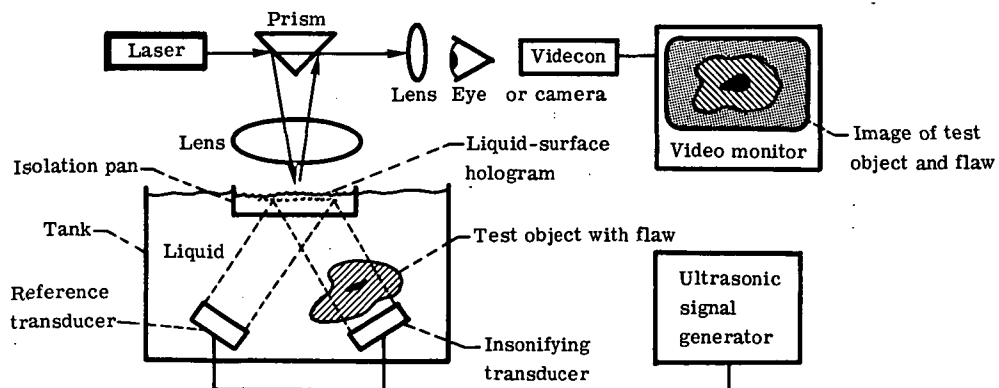
Ultrasonic Videography

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Object is illuminated with ultrasound. Ultrasound over an extensive area of object is detected to form an X-ray-like image.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Continuous or pulsed ultrasound at 1 to 10 MHz Transmission or attenuation by object variables Piezoelectric plate or crystal Direct visual, television monitor, and/or cinematography Direct
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Debonds, lack of bond, and delaminations Microporosity; grain and crystalline structure ----- Stress patterns ----- In-motion observation of flaws -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals, nonmetals, and liquids Bulk and internals ----- ----- Metal claddings and coatings, welds, spot welds, nuclear fuel plates, and electron population in semiconductors
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Immersion of test object required Crystal (diameter) limits area view to order of few centimeters Typical sensitivity to order of 0.1 centimeter Ambiguous response from interference fringes due to Fresnel-Fraunhofer effects -----
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 25 (ch. 3) ----- ----- ----- Immersion ultrasonics and ultrasonic holography



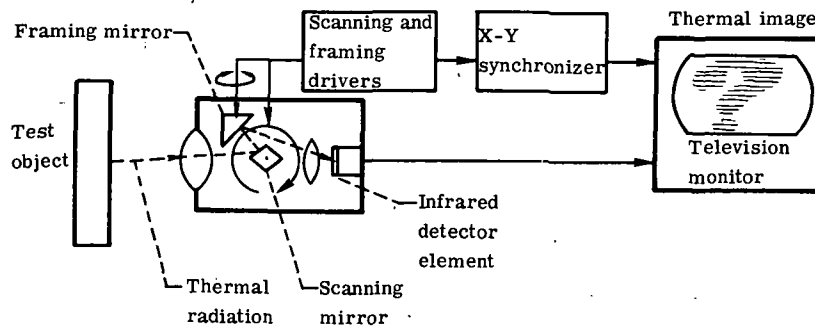
Ultrasonic Holography

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Ultrasound is transmitted through immersed object. Ultrasound modulated by object interacts with reference ultrasound waves to produce liquid-surface hologram of internal flaws.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	(Coherent) ultrasound Interference between transmitted and reference waves Laser holography of liquid-surface hologram Visual observation of reconstructed hologram Direct indication; based on library of sample images
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Cracks, debonds, voids, and inclusions Malstructure and/or misalignment ----- ----- ----- ----- Real-time acoustic imaging and object manipulation
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Range of solid materials Bulk and internal features ----- ----- Bonded and composite structures; biological materials
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Specimen or test object immersion in liquid required Limited area of object viewable due to transducer size Spatial resolution to order of 1 millimeter Scatter or attenuation can seriously limit utility. Size of detectable flaw increases with increasing thickness of object
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 25 (ch. 5) and 65 to 67 ----- ----- Acoustic holography Immersion ultrasonics and ultrasonic videography



Video Thermography

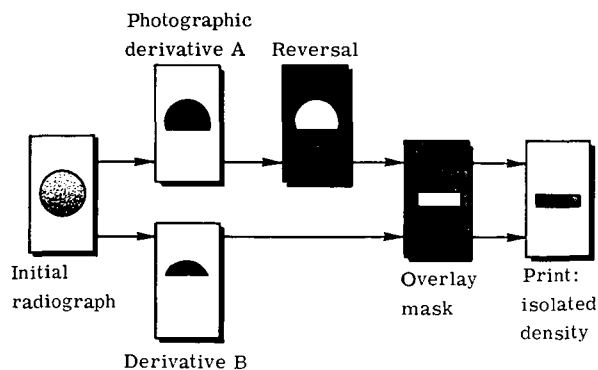
METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Thermal radiation from heated surface is imaged. Radiating surface is raster-scanned, and video image is composed from infrared detector signals.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Infrared radiation emitted by test object Surface-temperature variation or pattern Infrared-sensitive crystal Video or cathode-ray-tube image Comparative or differential; semiquantitative temperature indication
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Delaminations, debonds, and porosity ----- Thickness variations Emissivity and thermal-conductivity variations ----- Heat flow Thermal mapping and signature
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Metals, nonmetals, and composites Surfaces, entire bulks and objects, wide size range Quality monitoring of microcircuits Thermal signature of operating equipment Composite and laminated panels, solar cells, integrated circuits, and thermal insulators
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Visual access to surface required Mode and/or uniformity of heat application critical Temperature variation to order of 0.1°C Detector response in wide temperature range is nonlinear. Relatively slow response to thermal fluctuations
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 25 (ch. 14) ----- ----- ----- Infrared radiometry and thermochromic



SIGNAL-IMAGE ANALYSIS TECHNIQUES

Photographic Extraction

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Photoreprocessing is used to enhance details in images. Photographs and/or radiographs are reproduced with modified density or contrast values to obtain a derivative image.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Light Modulation of light by phototransparency Photoemulsion Photoreproduction or photoprint Interpretative aid
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Cracks, inclusions, voids, and porosity Structural irregularities and malstructure ----- ----- ----- ----- -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Radiographs, photographs, and thermographs Film transparencies ----- ----- Objects of original radiography
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Contact photoprinting Precise registration of overlay film images Enhances density differences to order of 0.02 photodensity units. Fine detail missed to degree of misregistration Control of photoprocessing, chemicals, and temperatures is critical. High quality in original image is required.
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	References 68 and 69 ----- ----- Pseudocolor (photographic) transform -----



Laser Filtering

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Film image is illuminated with laser light. Image is projected through spatial-Fourier filter, and enhanced version of image is reconstructed.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Beam of (coherent) laser light Impression of specimen image content on laser beam Fourier transform spatial filter in focal plane Photographic reconstruction Interpretive aid; depends on preselected transform parameters used for filtering
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	----- Structural attributes, properties, and contours ----- ----- ----- ----- Image detail extraction; image analysis and enhancement; pattern recognition and extraction
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Photographs and radiographs Film transparencies ----- Objects of original radiography ----- Nuclear fuel radiographs and reconnaissance photographs
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Adequate image detail must be in original image. Special spatial filter designs required Filter design based on known or assumed image content Depends on quality and content of original image -----
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	References 3 (ch. 4) and 70 ----- ----- Fourier transform holography and holographic image enhancement -----

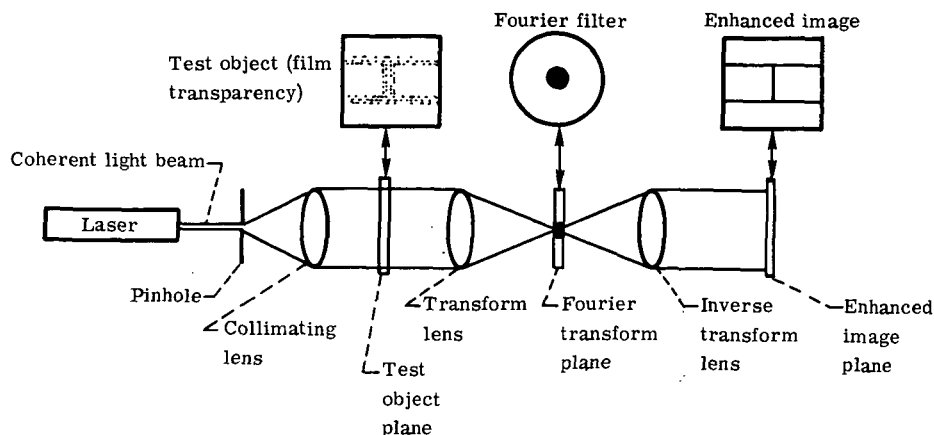
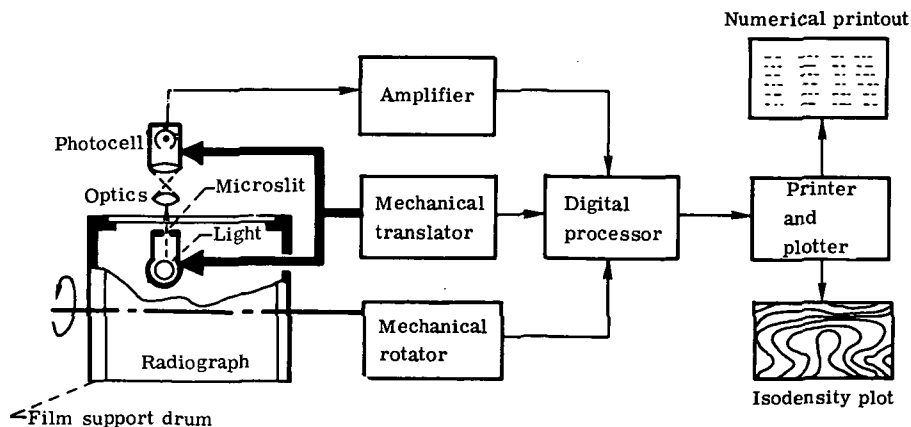


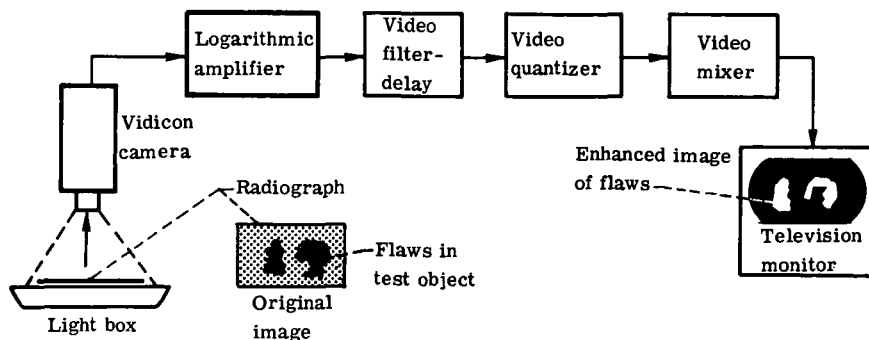
Image Scan Digitization

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Microspot raster-scanning of images is accomplished mechanically. Photograph or radiograph image elements are digitized, analyzed, and reproduced as enhanced hard-copy image derivatives.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Light Attenuation of light by density variations Photocell Plotter, printer, or facsimile reproducer Interpretational aid; depends on processing parameter settings for varying modes of enhancement
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	----- Structural anomalies and malstructure Density and thickness variations Elemental analysis ----- ----- Isotherms and thermal mapping; image edge enhancement, densitometry, and quantization
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Radiographs, photographs, thermographs, micrographs, spectrographs, and film transparencies and opaques ----- ----- ----- Objects of original radiography
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Film or transparency mounted on scanner drum or table Film or transparency sized to fit scanner format Usual sensitivity to order of 65 density increments Original image quality is limiting factor. Resolution varies with scanner spot size
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	References 71 and 72 ----- ----- Digital image processing Video enhancement, laser filtering, photographic extraction



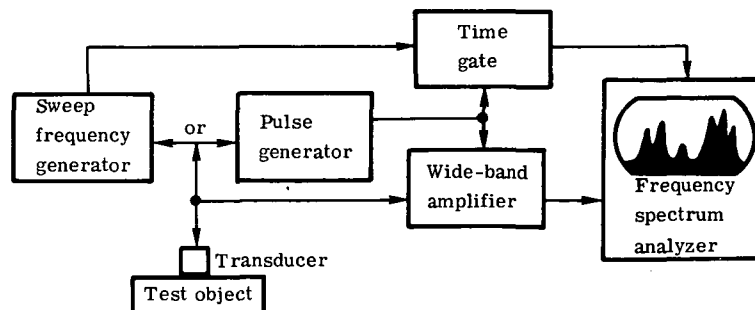
Video Enhancement

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Image is examined with video camera that converts image density values into signals that are enhanced electronically. Derivative image is displayed on television monitor.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Visible light Density variations in original image Videcon camera Television display Interpretative aid; depends on selection of mode of enhancement
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Cracks, voids, inclusions, porosity, etc. Malstructure and/or misalignment Dimensional measurements Density ----- ----- -----
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Radiographs, photographs, and metallographs Transparencies and opaque films ----- Combined with video radiography -----
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Presentation of image to camera required Special lens systems required for various uses Density increments to order of 0.05 photodensity units Usually senses to order of 32 density levels -----
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	References 73 and 74 ----- ----- ----- Photographic extraction, spot scanner-digitizer, and laser filter



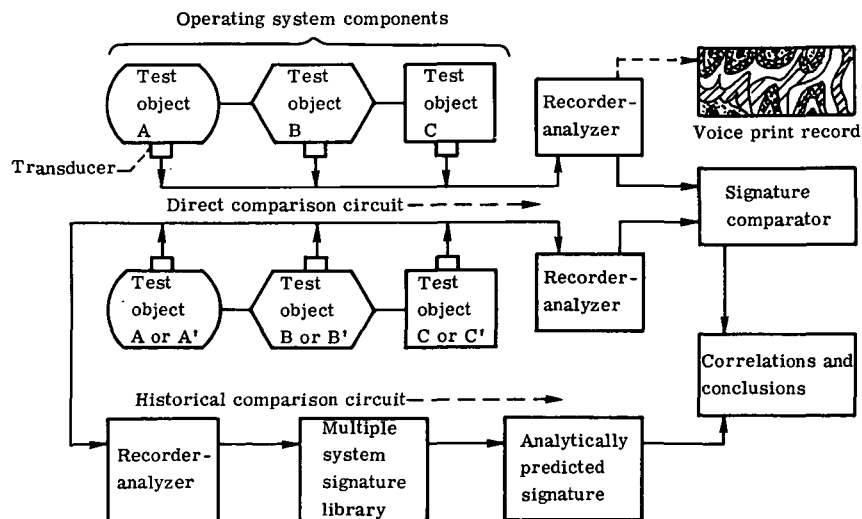
Ultrasonic Spectroscopy

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Object probed with multifrequency ultrasound. Response signals from ultrasonically probed object are analyzed for information on flaw geometry or material microstructure.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Injection of white or frequency-modulated ultrasound Modified transmitted or returned ultrasound spectrum Piezoelectric transducer Oscilloscope and spectrum analyzer Comparison or differential; based on file or library of frequency response patterns and spectra
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Size, shape, and orientation of discontinuities and inclusions Crystalline or amorphous microstructure Thickness gaging and grain-size measurement Acoustic attenuation and anisotropy Material identification and verification ----- Classification and testing frequency response signatures of various materials
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Crystalline or amorphous metals; nonmetals Near-surface features; simple geometric shapes ----- ----- Experimental and metallurgical specimens
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Contact and/or coupling and smooth surface required Probe frequency response is critical. Microstructural variations to order of 0.1 millimeter Presently an experimental technique -----
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 25 (ch. 2) ----- ----- Frequency spectrum analysis, waveform analysis -----



Sonic Signature Analysis

METHOD	CONCISE DESCRIPTION OF KEY PROCESS AND BASIC RESULT	Operating noise or vibration patterns emitted by engines and components are analyzed to indicate deviations or deterioration from preestablished norms.
PRINCIPLES	PROBE MEDIUM AND/OR ENERGY SOURCE NATURE OF SIGNAL AND/OR SIGNATURE DETECTION AND/OR SENSING METHOD INDICATION AND/OR RECORDING METHOD INTERPRETATION BASIS	Sounds activated by operation Sonic noise or vibration pattern and signature Microphones, accelerometers, and piezoelectric crystals Coplot of frequency, intensity, and time; voiceprint Comparative; requires library of standard signatures
OBJECTIVES	DISCONTINUITIES AND SEPARATIONS STRUCTURE OR MALSTRUCTURE DIMENSIONS AND METROLOGY PHYSICAL AND MECHANICAL PROPERTIES COMPOSITION AND CHEMICAL ANALYSES STRESS AND DYNAMIC RESPONSES SIGNATURE ANALYSIS	Cracks, pits, and gouges Roughness, loose material, and poor fit ----- ----- ----- Wear, degradation, abrasion, and/or misalignment Excessive or degenerate vibrations
APPLICATIONS	MATERIALS TO WHICH APPLIED FEATURES AND FORMS TO WHICH APPLIED PROCESS CONTROL APPLICATIONS IN SITU AND DIAGNOSTIC APPLICATIONS EXAMPLE STRUCTURES AND COMPONENTS	Mixed material combinations (Internal) functioning parts or components Monitoring of fabrication or processing noise Monitoring during operation and maintenance of engines Aircraft engines, motor vehicles, fluid systems, actuators, solenoids, electro-mechanical devices, and rotating or reciprocating machinery
LIMITATIONS	ACCESS, CONTACT, AND/OR PREPARATION PROBE AND OBJECT LIMITS SENSITIVITY AND/OR RESOLUTION INTERPRETATION LIMITS OTHER CONDITIONS AND LIMITS	Good sonic channels through part required Multiple, selectively placed probes required Resolution varies with ambient noise . Responds to mixed variables Filtering of extraneous frequencies required
REFERENCES	PRIMARY SOURCE MATERIAL BIBLIOGRAPHICAL MATERIAL STANDARDS AND SPECIFICATIONS RELATED TERMS RELATED TECHNIQUES	Reference 25 (ch. 7) ----- ----- Acoustic signature analysis Acoustic emission and sonic vibration



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ATTRIBUTE-PROPERTY-FLAW INDEX

Use the attribute-property-flaw index to locate specific items for which NDE techniques are sought. The index designates a "specific objective" for each item. Next, locate the specific objective in tables III to X to find techniques applicable to the item of interest. Thus, for example, if techniques for crack detection are sought, refer to "Cracks" in the index, for which the specific objectives are given as "Internal flaws" and "Surface-connected flaws." These specific-objective categories appear in each table (III to X), where applicable techniques are indicated.

Item	Specific Objective
Alloy identification or verification	Metallurgical content
Anneal	Stress, strain, and/or fatigue
Anisotropy	Matrix structure
Assembly errors	Gross structural flaws
Bond, poor	Internal flaws
Cavities	Surface-connected flaws
Chemical reaction	Chemical damage
Coating thickness	Thickness or density
Cohesive force	Magnetic properties
Cold-work	Stress, strain, and/or fatigue
Cold shuts	Surface-connected flaws
Color	Surface properties
Compressive strength or modulus	Mechanical properties
Conductivity, electrical	Electrical properties
Conductivity, thermal	Thermal properties
Contamination	Impurity concentrations
Contour	Dimensional variations
Corrosion	Chemical damage
Corrosion products	Physicochemical state
Crack initiation and propagation	Dynamic performance
Cracks	Internal flaws
Cracks	Surface-connected flaws
Crazing	Surface flaws
Creep	Dynamic performance
Crystalline structure	Microstructure
Cure, degree of	Physicochemical state

Item	Specific Objective
Damage, fatigue	Stress, strain, and/or fatigue
Damping	Dynamic performance
Debonds	Internal flaws
Definition, flaw	Signal or image analysis
Deformation	Gross structural flaws
Deformation, lattice	Microstructure
Deformation, plastic	Dynamic performance
Delaminations	Internal flaws
Densitometry (image)	Signal or image analysis
Density (variations)	Thickness or density
Depletion	Impurity concentrations
Depth, flaw	Displacement and/or position
Detection, elemental	Elemental analysis
Dielectric constant	Electrical properties
Diffusants	Impurity concentrations
Diffusion, isotope or tracer	Radioactive signature
Doping	Impurity concentrations
Dislocation, lattice	Microstructure
Display, flaw	Signal or image analysis
Dissipation factor	Electrical properties
Distribution, elemental	Elemental analysis
Distribution, field	Electromagnetic field
Distribution, filler or reinforcement	Matrix structure
Distribution, flaw	Signal or image analysis
Distribution, isotope or tracer	Radioactive signature
Distribution, temperature	Thermal field
Eccentricity	Dimensional variations
Embrittlement	Mechanical properties
Emission, sonic or ultrasonic	Acoustic signature
Emissivity	Surface properties
Enhancement, image	Signal or image analysis
Erosion	Mechanical damage
Excessive motion	Dynamic performance
Fatigue damage and/or life	Stress, strain, and/or fatigue
Ferromagnetism	Magnetic properties
Field distribution and/or pattern	Electromagnetic field
Filler distribution	Matrix structure

Item	Specific Objective
Film thickness	Thickness or density
Fit, poor	Small structural flaws
Flaw identification and mapping	Signal or image analysis
Flaw size and location	Displacement and/or position
Flow, heat	Thermal field
Folds	Surface-connected flaws
Foreign objects	Small structural flaws
Frequency analysis	Acoustic signature
Friction (effects)	Mechanical damage
Fusion, lack of	Internal flaws
Gap (size)	Displacement and/or position
Gouges	Surface flaws
Grain structure and size	Matrix structure
Hardness	Mechanical properties
Heat contours	Thermal field
Heat flow and leaks	Thermal field
Heat treat	Stress, strain, and/or fatigue
Holes, through	Small structural flaws
Hot spots	Thermal field
Hot tears	Internal flaws
Hydrogen embrittlement	Other damage
Identification, alloy	Metallurgical content
Identification, element	Elemental analysis
Identification, flaw	Signal or image analysis
Image enhancement	Signal or image analysis
Imbedation	Surface flaws
Impregnation	Matrix structure
Inclusions	Internal flaws
Inclusions	Surface-connected flaws
Inclusions	Surface flaws
Index, refraction	Surface properties
Inhomogeneity	Matrix structure
Ion concentration	Physicochemical state
Isotherms	Thermal field
Isotope distribution	Radioactive signature

Item	Specific Objective
Lack of fusion	Internal flaws
Lack of seal	Small structural flaws
Laps	Surface-connected flaws
Lattice structure or strain	Microstructure
Layer, thickness	Thickness or density
Leaks	Small structural flaws
Leaks, heat	Thermal field
Life, fatigue	Stress, strain, and/or fatigue
Linear measurement	Displacement and/or position
Location, flaw	Displacement and/or position
Loose parts or particles	Small structural flaws
Magnetism	Magnetic properties
Malformation	Gross-structural flaws
Mapping, flaw	Signal or image analysis
Mass (variations)	Dimensional variations
Measurement	Displacement and/or position
Misalignment	Gross structural flaws
Missing parts	Gross structural flaws
Moduli	Mechanical properties
Moisture content	Physicochemical state
Molecular structure	Microstructure
Motion, excessive	Dynamic performance
Noise	Acoustic signature
Nonuniformity	Dimensional variations
Ordering, part	Gross structural flaws
Orientation, flaw	Displacement and/or position
Orientation, grain	Matrix structure
Pattern, electric field	Electromagnetic field
Pattern recognition	Signal or image analysis
Permeability	Magnetic properties
Phases, grain	Matrix structure
Phase transformation	Chemical damage
Pinholes	Surface-connected flaws
Pitting	Surface flaws
Plating (thickness)	Thickness or density

Item	Specific Objective
Plastic deformation	Dynamic performance
Poisson's ratio	Mechanical properties
Polarization	Magnetic properties
Poor bond	Internal flaws
Poor spacing	Gross structural flaws
Pores	Internal flaws
Porosity	Surface-connected flaws
Potential, electric	Electromagnetic field
Products, reaction	Metallurgical content
Profile, element	Elemental analysis
Radiation damage	Other damage
Reaction products	Physicochemical state
Refraction index	Surface properties
Reflectivity	Surface properties
Reinforcement (composite)	Matrix structure
Residual stress	Stress, strain, and/or fatigue
Resistivity	Electrical properties
Roughness	Surface flaws
Scratches	Surface flaws
Seal, lack of	Small structural flaws
Seams	Surface-connected flaws
Segregation	Internal flaws
Segregation	Matrix structure
Separation	Displacement and/or position
Separations	Internal flaws
Shape	Dimensional variations
Shear modulus and/or strength	Mechanical properties
Sheet thickness	Thickness or density
Shrinkage	Internal flaws
Signal correlation	Signal or image analysis
Sinter and/or porosity	Matrix structure
Size, flaw	Displacement and/or position
Size, grain	Matrix structure
Size variations	Dimensional variations
Sonic emission	Acoustic signature
Sonic velocity	Mechanical properties
Sorting, alloy	Metallurgical content

Item	Specific Objective
Spacing	Gross structural flaws
Spalling	Mechanical damage
Spectrum, frequency	Acoustic signature
Strain, crystal	Microstructure
Strain, lattice	Internal flaws
Strain, residual	Stress, strain, and/or fatigue
Strength, field	Electromagnetic field
Stress corrosion	Chemical damage
Stress distribution	Stress, strain, and/or fatigue
Stress, residual	Stress, strain, and/or fatigue
Structure, grain	Matrix structure
Structure, lattice	Internal flaws
Structure, molecular	Microstructure
Temper	Mechanical properties
Temperature (distribution)	Thermal field
Tensile modulus and strength	Mechanical properties
Thermal time constant	Thermal properties
Thermoelectric potential	Thermal properties
Thickness (variations)	Thickness or density
Through holes	Small structural flaws
Tracer (isotope)	Radioactive signature
Ultrasonic emission	Acoustic signature
Vacancy, lattice	Microstructure
Variations, size and mass	Dimensional variations
Velocity	Mechanical properties
Verification, alloy	Metallurgical content
Vibration	Dynamic performance
Vibration characteristics	Acoustic signature
Voids	Internal flaws
Voltage breakdown (effects)	Other damage
Wall thickness	Thickness or density
Wear	Mechanical damage
Work hardening	Mechanical properties

TABLE III. - ATTRIBUTES MEASURED OR DETECTED WITH MECHANICAL-OPTICAL NONDESTRUCTIVE EVALUATION TECHNIQUES

Objectives of nondestructive evaluation		Nondestructive evaluation techniques ^a									
Main objectives	Specific objectives	Visual-optical	Holointerferometry	Photo-elastic coating	Brittle coating	Strain gage	Micro-hardness	Liquid penetrant	Volatile liquid	Filtered particle	Leak detection
Discontinuities and separations	Surface flaws	A	C	C			C				
	Surface-connected flaws	A	B	B				A	B	A	C
	Internal flaws		A	C							
Structure or mal-structure	Microstructure										
	Matrix structure										
	Small structural flaws	A	C					C			A
	Gross structural flaws	A	C								
Dimensions and metrology	Displacement and/or position	C									
	Dimensional variations	C									
	Thickness or density		B								
Physical and mechanical properties	Electrical properties										
	Magnetic properties										
	Thermal properties										
	Mechanical properties						B				
	Surface properties	A									
Chemical composition and analysis	Elemental analysis										
	Impurity concentrations										
	Metallurgical content										
	Physicochemical state										
Stress and dynamic responses	Stress, strain, and/or fatigue		A	A	A	A					
	Mechanical damage	A									
	Chemical damage	B									
	Other damage										
	Dynamic performance	C	B	B		B					
Signature analysis	Electromagnetic field										
	Thermal field										
	Acoustic signature										
	Radioactive signature										
	Signal or image analysis										

^aA: very satisfactory technique; B: satisfactory technique; C: restricted usage; D: potential usage; E: experimental.

TABLE IV. - ATTRIBUTES MEASURED OR DETECTED WITH PENETRATING RADIATION NONDESTRUCTIVE EVALUATION TECHNIQUES

Objectives of nondestructive evaluation		Nondestructive evaluation techniques ^a							
Main objectives	Specific objectives	X-radiography	Gamma radiography	Neutron radiography	Penetrating radiometry	Backscatter radiometry	Autoradiography	Radioactive penetrant	Positron annihilation
Discontinuities and separations	Surface flaws								
	Surface-connected flaws							A	
	Internal flaws	B	C	C	C				
Structure or mal-structure	Microstructure								E
	Matrix structure								
	Small structural flaws	B	C	C					
	Gross structural flaws	A	A	A					
Dimensions and metrology	Displacement and/or position	A	A	A					
	Dimensional variations	A	A	A					
	Thickness or density	C	C	C	A	A	A		
Physical and mechanical properties	Electrical properties								
	Magnetic properties								
	Thermal properties								
	Mechanical properties								E
	Surface properties								
Chemical composition and analysis	Elemental analysis					C	B		
	Impurity concentrations								
	Metallurgical content								
	Physicochemical state			C					
Stress and dynamic responses	Stress, strain, and/or fatigue								B
	Mechanical damage	C	D	C	B		A	B	
	Chemical damage				D	D	B	C	
	Other damage			D					
	Dynamic performance								
Signature analysis	Electromagnetic field								
	Thermal field								
	Acoustic signature								
	Radioactive signature				B		A	C	
	Signal or image analysis								

^a A: very satisfactory technique; B: satisfactory technique; C: restricted usage; D: potential usage; E: experimental.

TABLE V. - ATTRIBUTES MEASURED OR DETECTED WITH ELECTROMAGNETIC-ELECTRONIC NONDESTRUCTIVE EVALUATION TECHNIQUES

Objectives of nondestructive evaluation		Nondestructive evaluation techniques ^a										
Main objectives	Specific objectives	Static magnetic field	Magnetic particle	Nuclear magnetic resonance	Barkhausen effect	Eddy current	Electric current	Electrified particle	Corona discharge	Dielectric	Exo-electron emission	Micro-wave radiation
Discontinuities and separations	Surface flaws							A			A	
	Surface-connected flaws	A	A	D	B	A	A	A	A	C		C
	Internal flaws	C	C			B	B					C
Structure or mal-structure	Microstructure			A								
	Matrix structure	C			A	C				C		
	Small structural flaws											
	Gross structural flaws											
Dimensions and metrology	Displacement and/or position											C
	Dimensional variations											
	Thickness or density	A				A	B			B		A
Physical and mechanical properties	Electrical properties					A	A			A		B
	Magnetic properties	A	C			A						
	Thermal properties											
	Mechanical properties	C										
	Surface properties										A	
Chemical composition and analysis	Elemental analysis			C								
	Impurity concentrations			C					C		C	C
	Metallurgical content	B				B						
	Physicochemical state									A		B
Stress and dynamic responses	Stress, strain, and/or fatigue			C	B	B	C				A	
	Mechanical damage						B					
	Chemical damage						B					
	Other damage									B		
	Dynamic performance						B	C				C
Signature analysis	Electromagnetic field	D	C									
	Thermal field											
	Acoustic signature											
	Radioactive signature											
	Signal or image analysis											

^a A: very satisfactory technique; B: satisfactory technique; C: restricted usage; D: potential usage; E: experimental.

TABLE VI. - ATTRIBUTES MEASURED OR DETECTED WITH SONIC-ULTRASONIC NONDESTRUCTIVE EVALUATION TECHNIQUES

Objectives of nondestructive evaluation		Nondestructive evaluation techniques ^a								
Main objectives	Specific objectives	Acoustic impact	Sonic vibration	Eddy sonic vibration	Acoustic emission	Pulse-echo ultrasonics	Transmission ultrasonics	Resonance ultrasonics	Surface-wave ultrasonics	Critical-angle ultrasonics
Discontinuities and separations	Surface flaws								A	B
	Surface-connected flaws	D				A	C		A	
	Internal flaws	C	C	B		A	B	C		
Structure or mal-structure	Microstructure									
	Matrix structure					B		C		B
	Small structural flaws	B	B	B	A					
	Gross structural flaws	C								
Dimensions and metrology	Displacement and/or position					A	C		C	
	Dimensional variations	B	B						C	
	Thickness or density	C	C			C	C	A	B	
Physical and mechanical properties	Electrical properties									
	Magnetic properties									
	Thermal properties									
	Mechanical properties		A	D		B	B	A		B
	Surface properties									
Chemical composition and analysis	Elemental analysis									
	Impurity concentrations									
	Metallurgical content									
	Physicochemical state									
Stress and dynamic responses	Stress, strain, and/or fatigue			D	B				B	A
	Mechanical damage			D		C		C		
	Chemical damage			D						
	Other damage									
	Dynamic performance	C	C	C		A	A			D
Signature analysis	Electromagnetic field									
	Thermal field									
	Acoustic signature	D	B	C	A					
	Radioactive signature									
	Signal or image analysis									

^a A: very satisfactory technique; B: satisfactory technique; C: restricted usage; D: potential usage; E: experimental.

TABLE VII. - ATTRIBUTES MEASURED OR DETECTED WITH THERMAL
NONDESTRUCTIVE EVALUATION TECHNIQUES

Objectives of nondestructive evaluation		Nondestructive evaluation techniques ^a				
Main objectives	Specific objectives	Contact thermometry	Thermoelectric probe	Infrared radiometry	Thermochromic	Electrothermal
Discontinuities and separations	Surface flaws	C				
	Surface-connected flaws		B	B	B	
	Internal flaws			A	C	B
Structure or mal-structure	Microstructure					
	Matrix structure		C			
	Small structural flaws					
	Gross structural flaws					
Dimensions and metrology	Displacement and/or position					
	Dimensional variations					
	Thickness or density	C	C	C	C	C
Physical and mechanical properties	Electrical properties					C
	Magnetic properties					
	Thermal properties	B	C	A	C	C
	Mechanical properties	D				
	Surface properties		C	A		
Chemical composition and analysis	Elemental analysis					
	Impurity concentrations		C			
	Metallurgical content					
	Physicochemical state					
Stress and dynamic responses	Stress, strain, and/or fatigue					
	Mechanical damage					
	Chemical damage					
	Other damage					
	Dynamic performance					C
Signature analysis	Electromagnetic field					
	Thermal field	C		A	B	
	Acoustic signature					
	Radioactive signature					
	Signal or image analysis					

^aA: very satisfactory technique; B: satisfactory technique; C: restricted usage; D: potential usage; E: experimental.

TABLE VIII. - ATTRIBUTES MEASURED OR DETECTED WITH CHEMICAL-ANALYTICAL NONDESTRUCTIVE EVALUATION TECHNIQUES

Objectives of nondestructive evaluation		Nondestructive evaluation techniques ^a										
Main objectives	Specific objectives	Chemical spot test	Electrolytic probe	Laser probe	Ion scatter	Ion probe	Auger analysis	X-ray fluorescence	X-ray diffraction	Neutron activation	Charged-particle activation	Mössbauer analysis
Discontinuities and separations	Surface flaws		C									E
	Surface-connected flaws											
	Internal flaws											
Structure or mal-structure	Microstructure			B		B			B			A
	Matrix structure						B		B			
	Small structural flaws											
	Gross structural flaws											
Dimensions and metrology	Displacement and/or position											
	Dimensional variations											
	Thickness or density							C			E	D
Physical and mechanical properties	Electrical properties											
	Magnetic properties											B
	Thermal properties											
	Mechanical properties											
	Surface properties											
Chemical composition and analysis	Elemental analysis	B	D	C	B	B	C	B		B	B	C
	Impurity concentrations		D	B	B	B	C	B	C		B	
	Metallurgical content	B		C	D	D					C	
	Physicochemical state											
Stress and dynamic responses	Stress, strain, and/or fatigue		E				E		A			
	Mechanical damage											
	Chemical damage			B	B	B	D	B	C	C		C
	Other damage											
	Dynamic performance											
Signature analysis	Electromagnetic field											
	Thermal field											
	Acoustic signature											
	Radioactive signature									D		
	Signal or image analysis											

^aA: very satisfactory technique; B: satisfactory technique; C: restricted usage; D: potential usage; E: experimental.

TABLE IX. - ATTRIBUTES MEASURED OR DETECTED WITH IMAGE GENERATION NONDESTRUCTIVE EVALUATION TECHNIQUES

Objectives of nondestructive evaluation		Nondestructive evaluation techniques ^a									
Main objectives	Specific objectives	Photo-imaging	Film radiography	Xeroradiography	Track-edge radiography	Fluoroscopy	Video radiography	Immersion ultrasonics	Ultrasonic videography	Ultrasonic holography	Video thermography
Discontinuities and separations	Surface flaws	A									
	Surface-connected flaws	C	C					A	C	B	B
	Internal flaws		A	B	C	C	B	A	B	B	B
Structure or mal-structure	Microstructure				E				E		
	Matrix structure							C	D		
	Small structural flaws		B	B		B	B	C	C	C	
	Gross structural flaws		A	A		A	B				
Dimensions and metrology	Displacement and/or position		A	A		C	C	C	C		
	Dimensional variations		A	B		C	B				
	Thickness or density		C	C		D	C	C	D		C
Physical and mechanical properties	Electrical properties										
	Magnetic properties										
	Thermal properties										C
	Mechanical properties							D			
	Surface properties	A									C
Chemical composition and analysis	Elemental analysis										
	Impurity concentrations										
	Metallurgical content										
	Physicochemical state										
Stress and dynamic responses	Stress, strain, and/or fatigue								E		
	Mechanical damage		D	D		D	D				
	Chemical damage										
	Other damage										
	Dynamic damage					C	B		D	D	
Signature analysis	Electromagnetic field										
	Thermal field	C									A
	Acoustic signature										
	Radioactive signature	D	A	D		D	A				
	Signal or image analysis				B		B	D	B	B	B

^a A: very satisfactory technique; B: satisfactory technique; C: restricted usage; D: potential usage; E: experimental.

TABLE X. - ATTRIBUTES MEASURED OR DETECTED WITH SIGNAL-IMAGE ANALYSIS

NONDESTRUCTIVE EVALUATION TECHNIQUES

Objectives of nondestructive evaluation		Nondestructive evaluation techniques ^a					
Main objectives	Specific objectives	Photo-graphic extrac-tion	Laser filter-ing	Image scan digitiza-tion	Video enhance-ment	Ultrasonic spectroscopy	Sonic signature analysis
Discontinuities and separations	Surface flaws						
	Surface-connected flaws	B	D	D	B		
	Internal flaws	B	B	C	B		
Structure or mal-structure	Microstructure						
	Matrix structure					E	
	Small structural flaws	C	C	C	B		B
	Gross structural flaws	C	C	C	C		C
Dimensions and metrology	Displacement and/or position	C	C	C	B		
	Dimensional variations						
	Thickness or density						
Physical and me- chanical properties	Electrical properties						
	Magnetic properties						
	Thermal properties						
	Mechanical properties						
	Surface properties						
Chemical composi-tion and analysis	Elemental analysis						
	Impurity concentrations						
	Metallurgical content						
	Physicochemical state						
Stress and dynamic responses	Stress, strain, and/or fatigue						
	Mechanical damage	D	D	D	D		B
	Chemical damage						
	Other damage						
	Dynamic performance				B		A
Signature analysis	Electromagnetic field						
	Thermal field						
	Acoustic signature					A	A
	Radioactive signature				A		
	Signal or image analysis	B	B	B	A	A	A

^aA: very satisfactory technique; B: satisfactory technique; C: restricted usage; D: potential usage; E: experimental.

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